

FIG. 1A

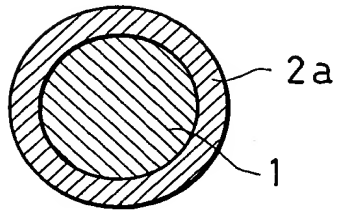


FIG. 1B

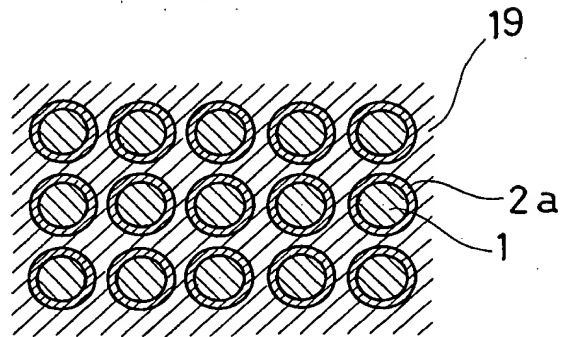


FIG. 1C

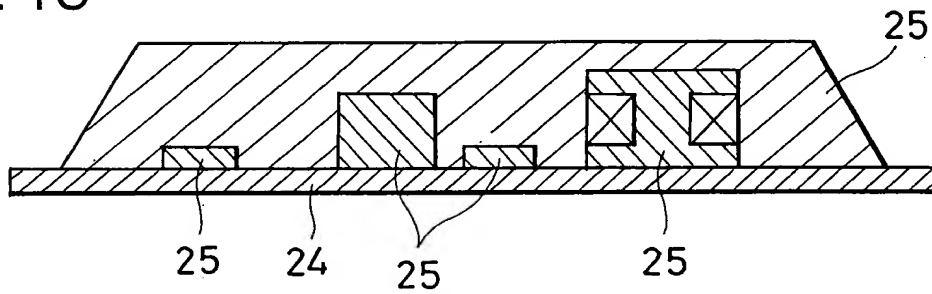


FIG. 1D

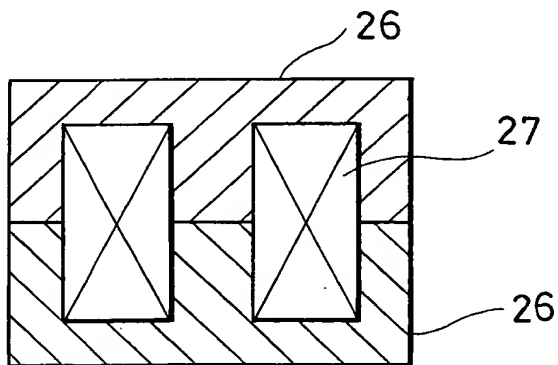
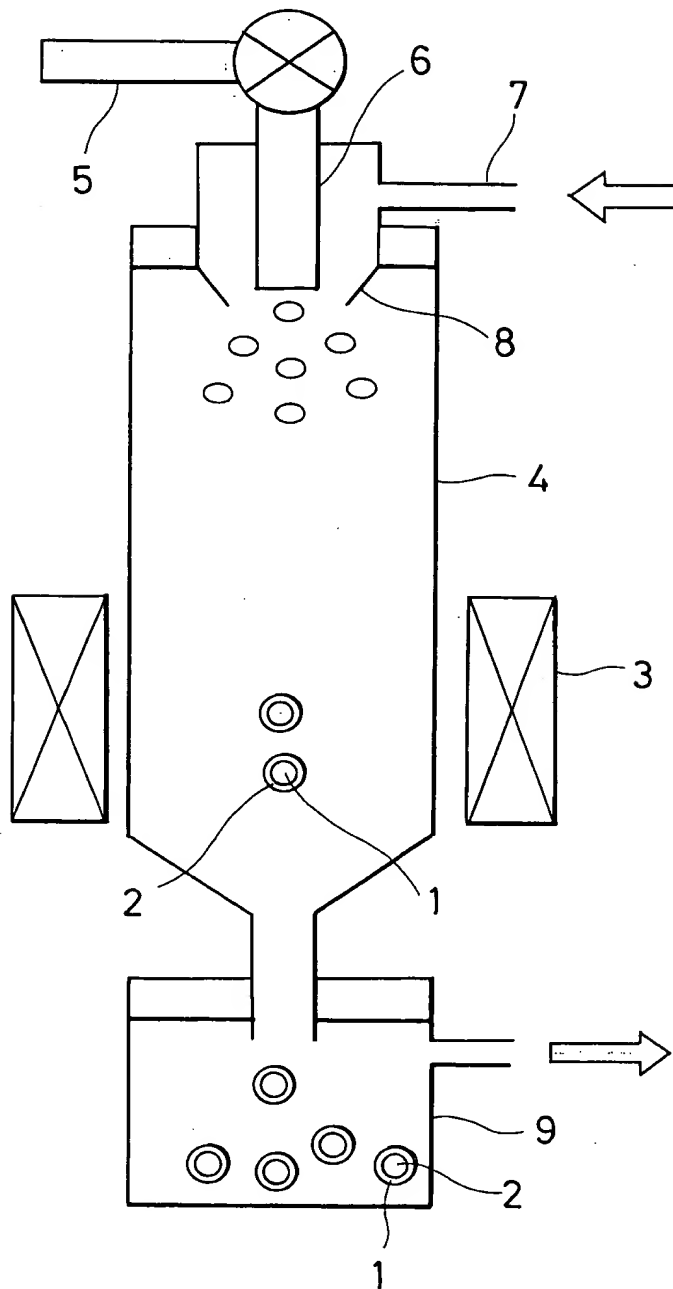


FIG. 2



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FIG. 3A

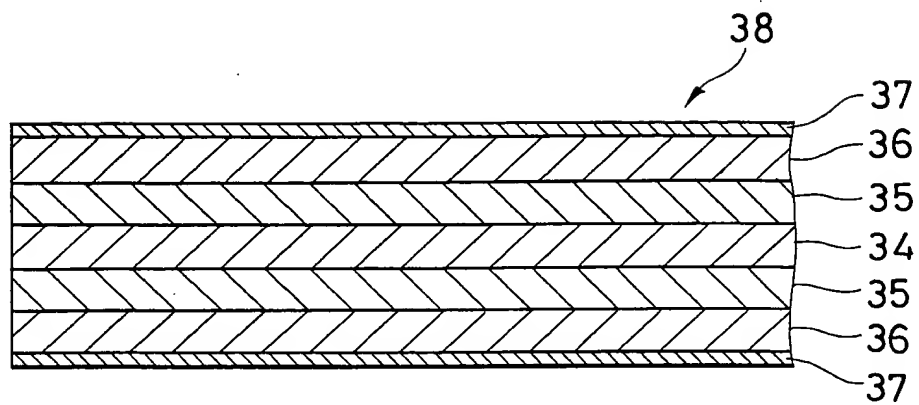


FIG. 3B



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FIG. 4A

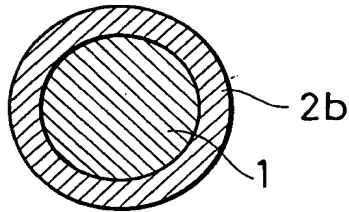


FIG. 4B

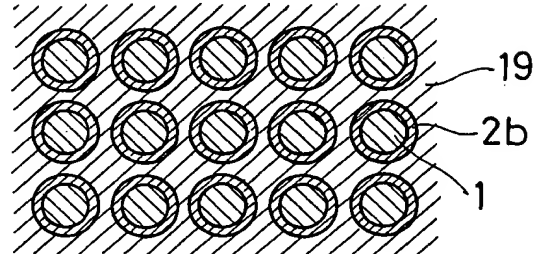


FIG. 4C

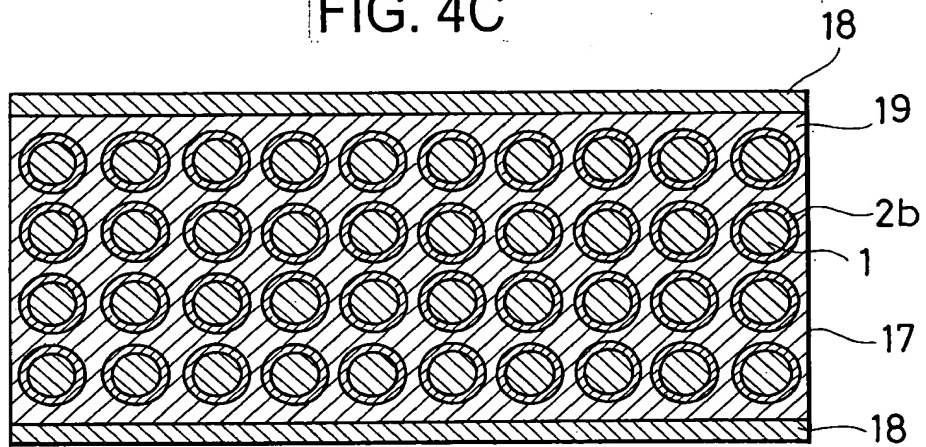
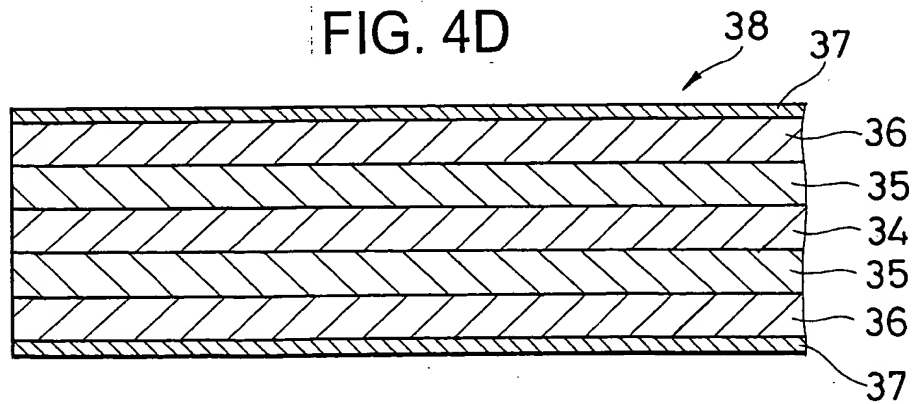


FIG. 4D



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FIG. 5A

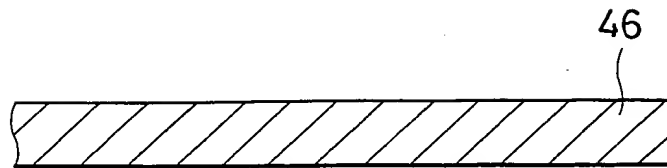


FIG. 5B

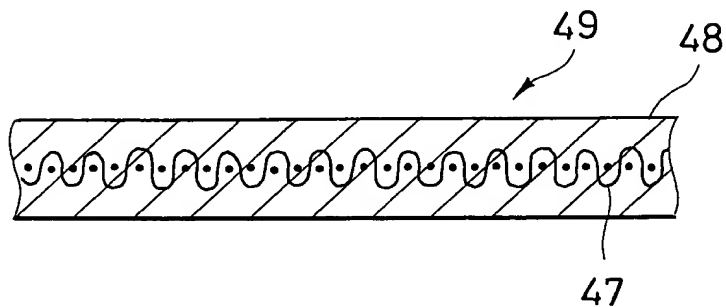


FIG. 5C

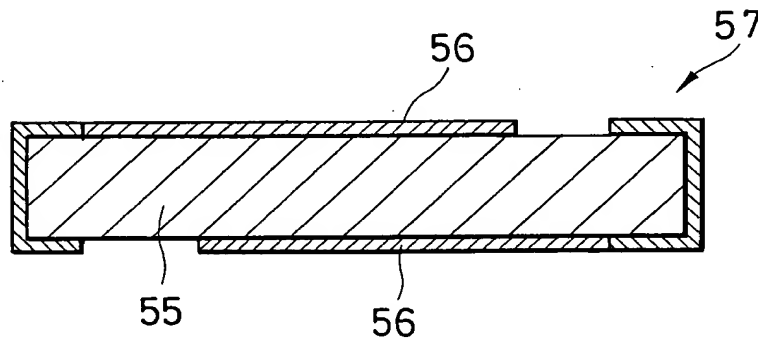
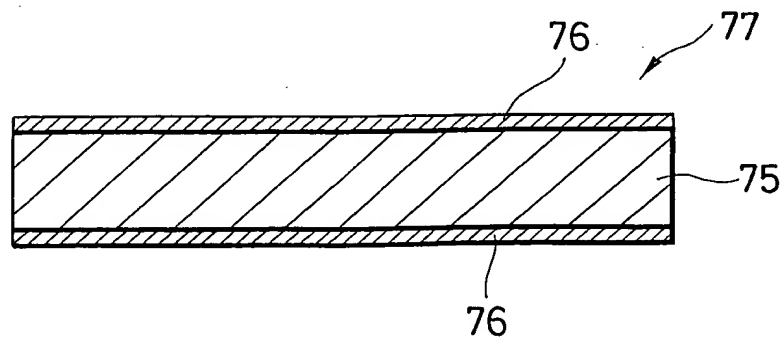
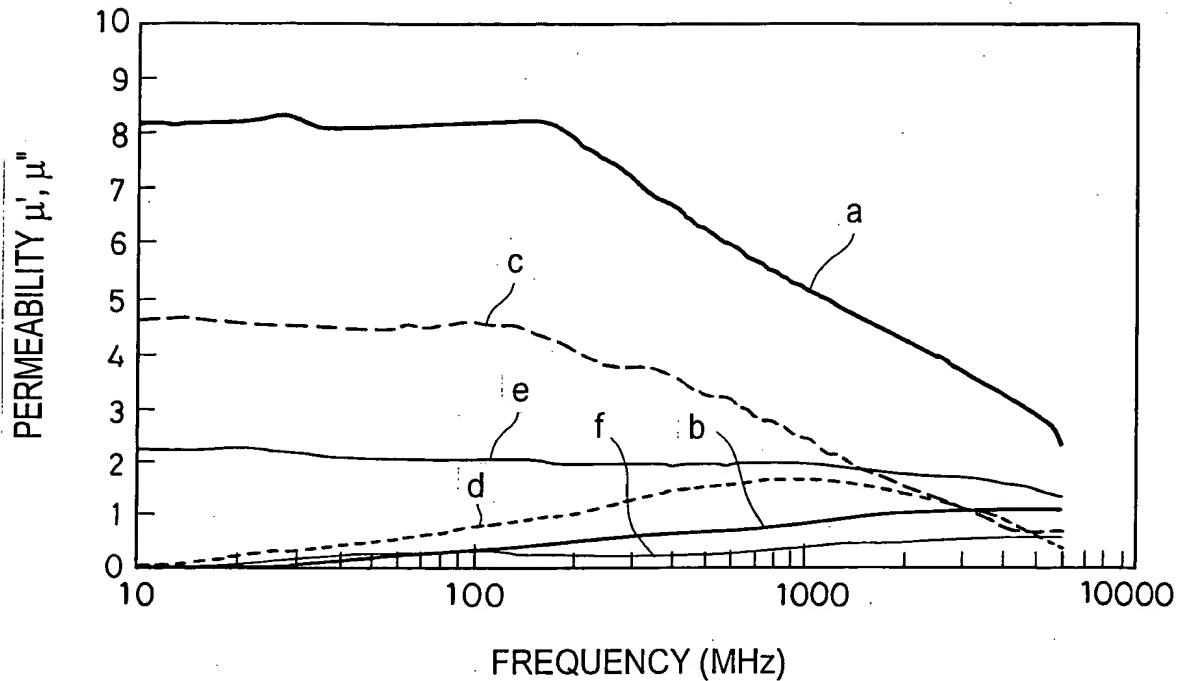


FIG. 5D



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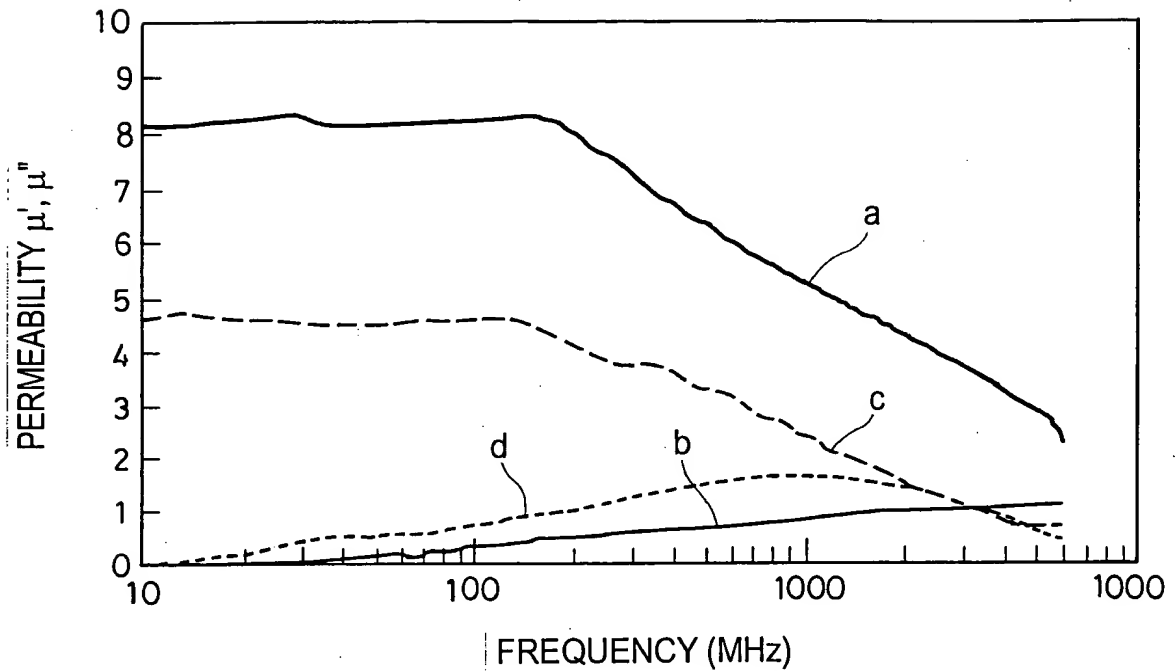
FIG. 6



- a: INVENTION, μ'
BARIUM TITANATE-COATED IRON POWDER COMPOSITE MATERIAL
- b: INVENTION, μ''
BARIUM TITANATE-COATED IRON POWDER COMPOSITE MATERIAL
- c: COMPARISON 1, μ'
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- d: COMPARISON 1, μ''
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- e: COMPARISON 2, μ'
LOW-PERMEABILITY FERRITE COMPOSITE MATERIAL
- f: COMPARISON 2, μ''
LOW-PERMEABILITY FERRITE COMPOSITE MATERIAL

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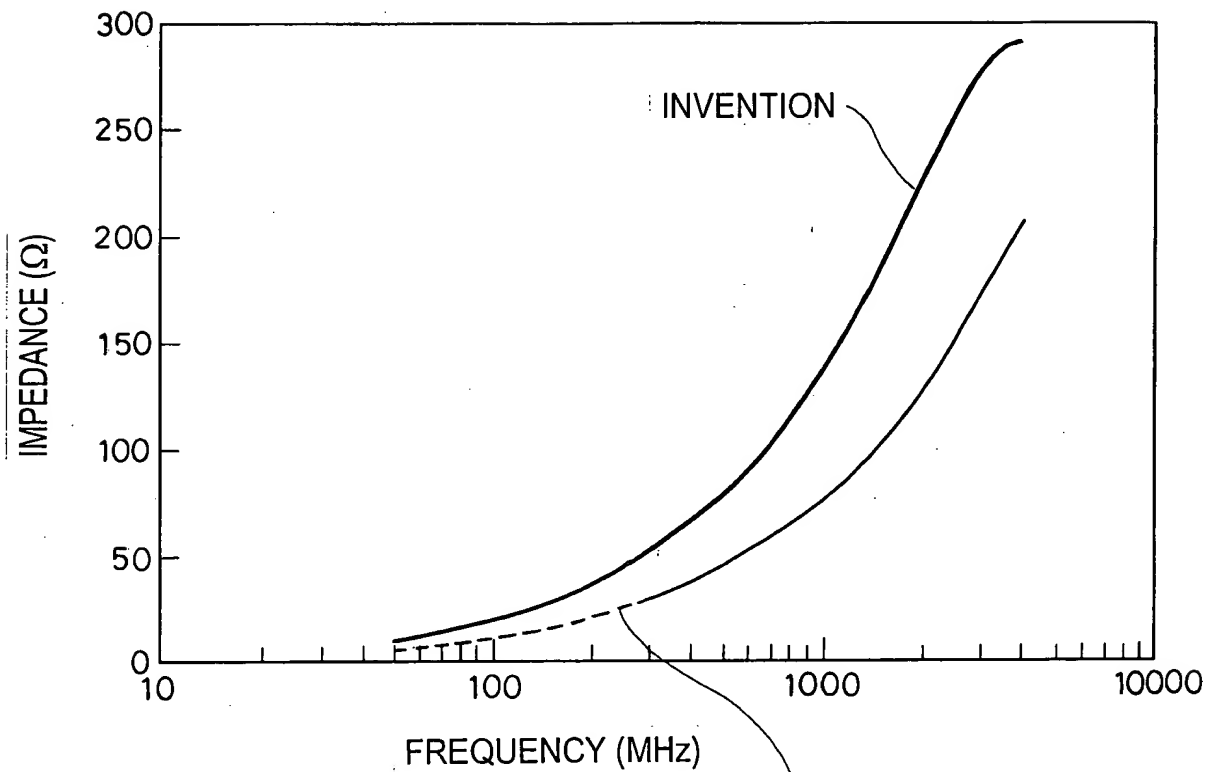
FIG. 7



- a: INVENTION, μ'
GLASS-COATED IRON POWDER COMPOSITE MATERIAL
- b: INVENTION, μ''
GLASS-COATED IRON POWDER COMPOSITE MATERIAL
- c: COMPARISON 1, μ'
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL
- d: COMPARISON 1, μ''
HIGH-PERMEABILITY FERRITE COMPOSITE MATERIAL

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FIG. 8



COMPARISON (HIGH-FREQUENCY BEADS USING FERRITE
COMPOSITE MAGNETIC SUBSTRATE)

FIG. 9

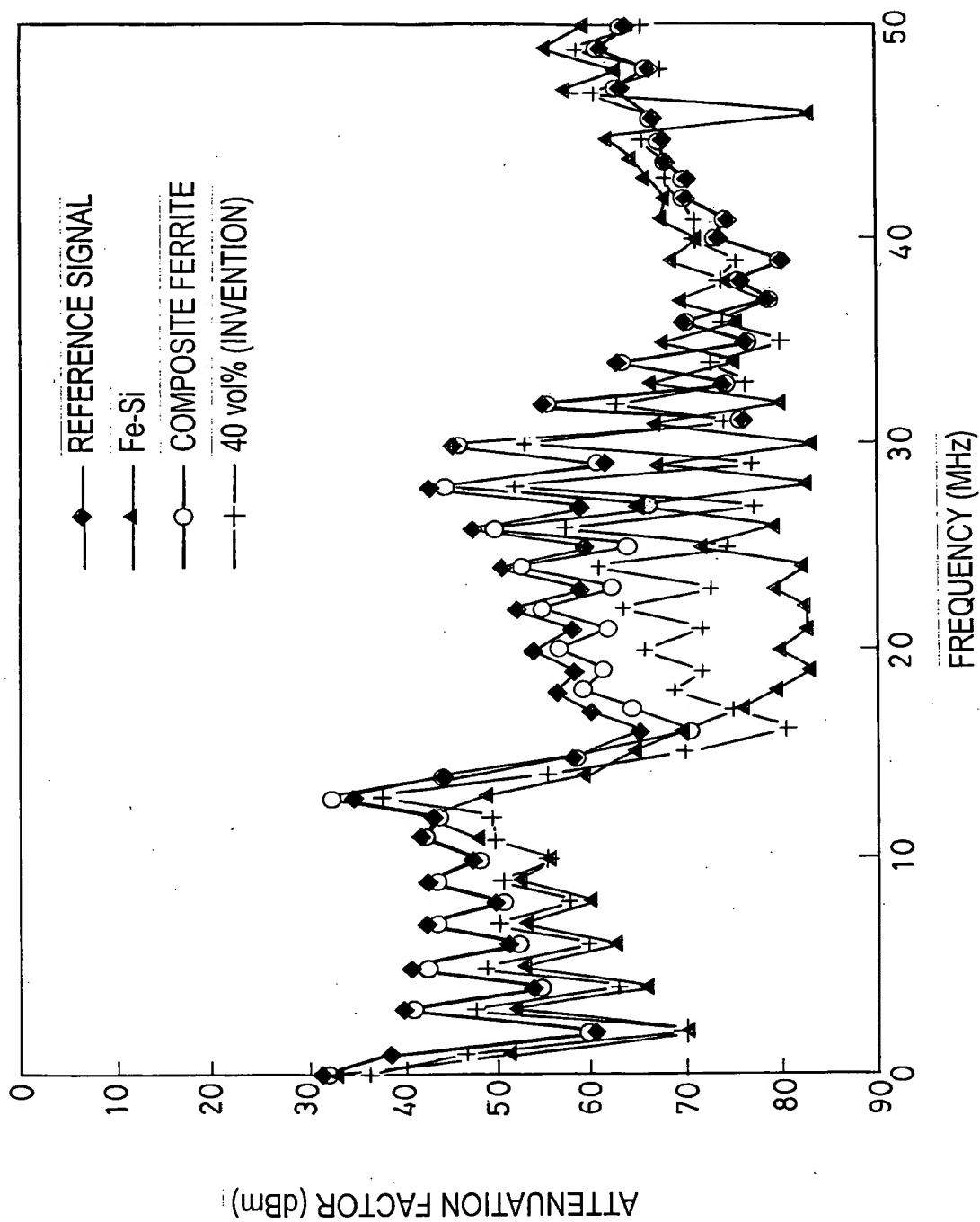
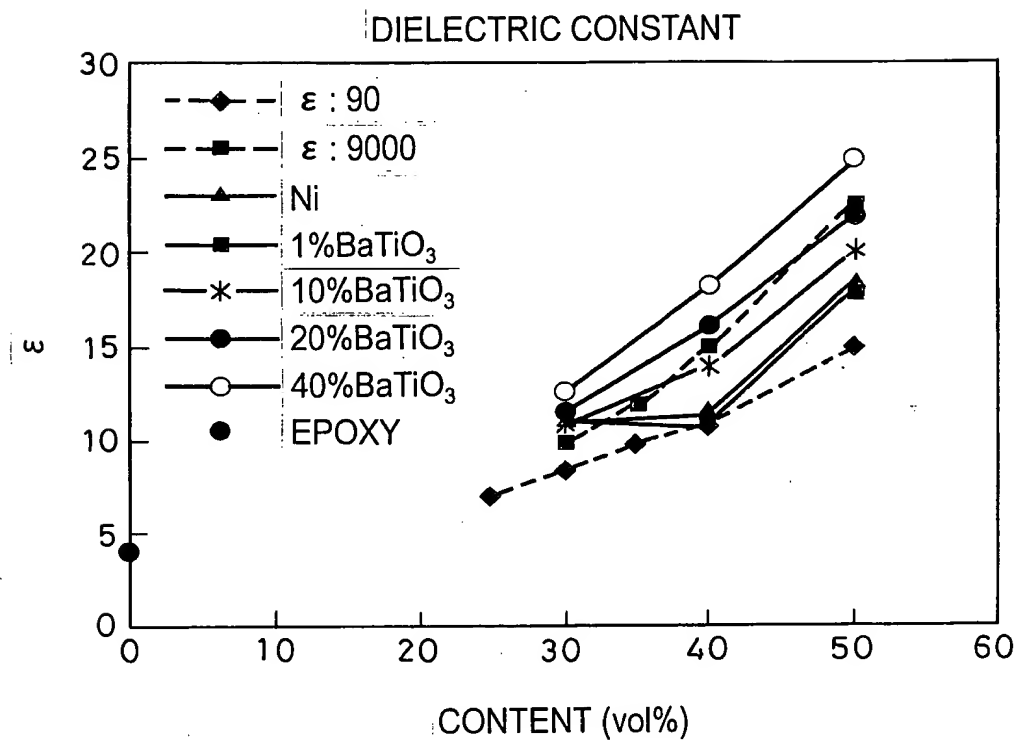
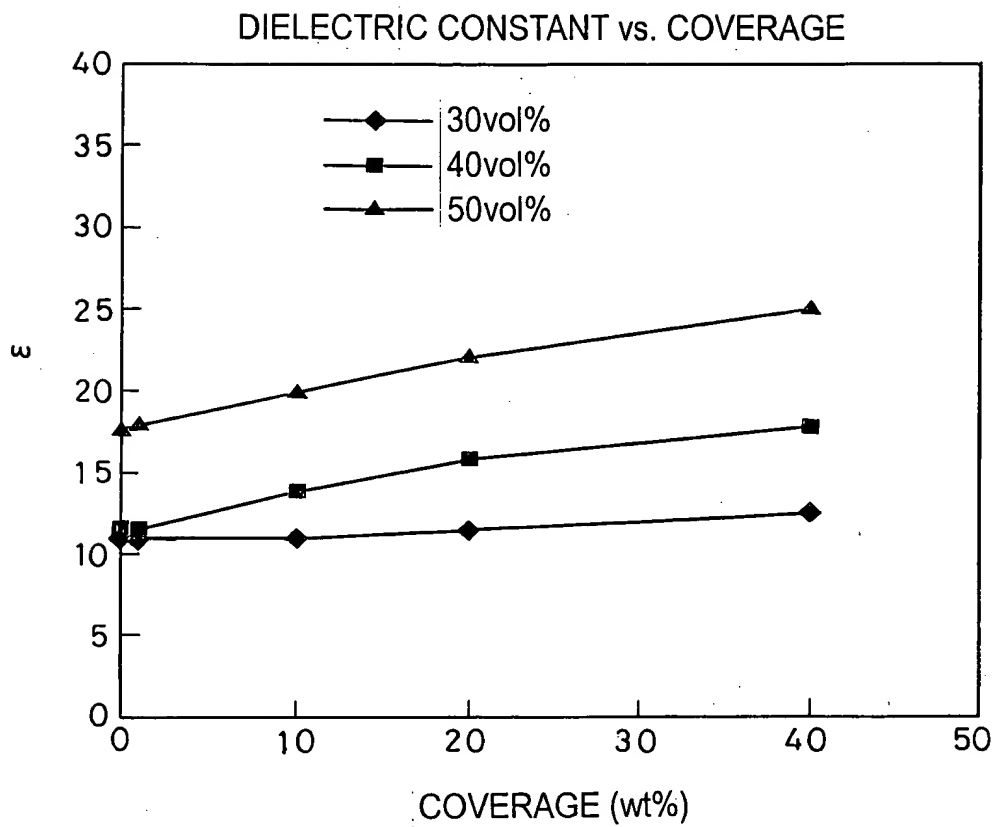


FIG. 10



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FIG. 11



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FIG. 12

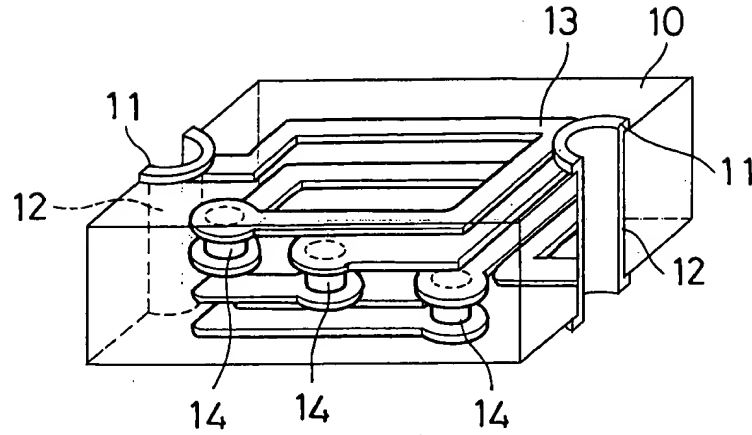
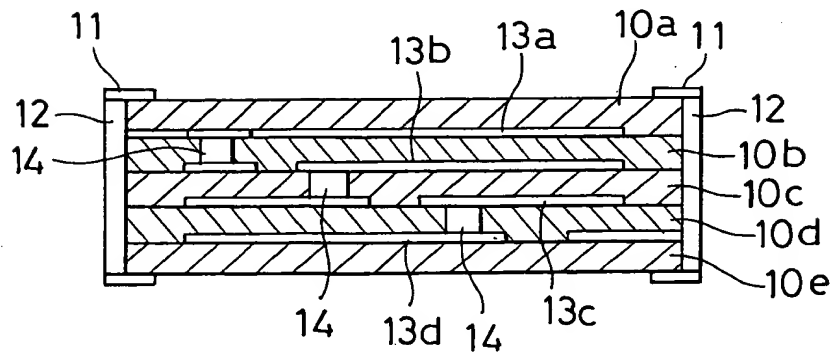


FIG. 13



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FIG. 14

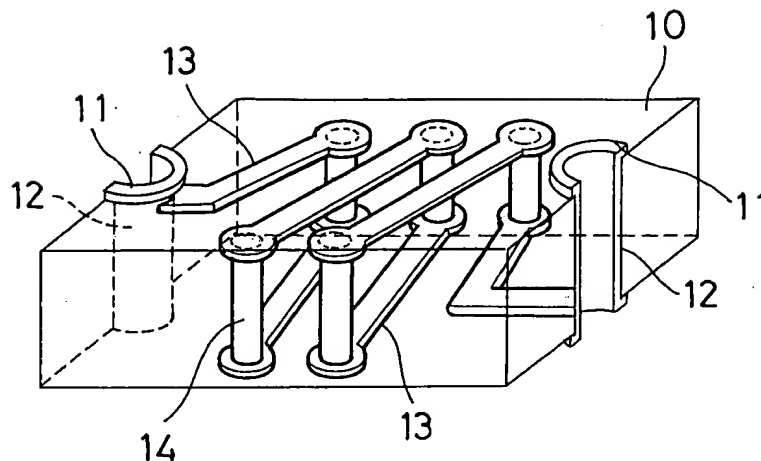


FIG. 15

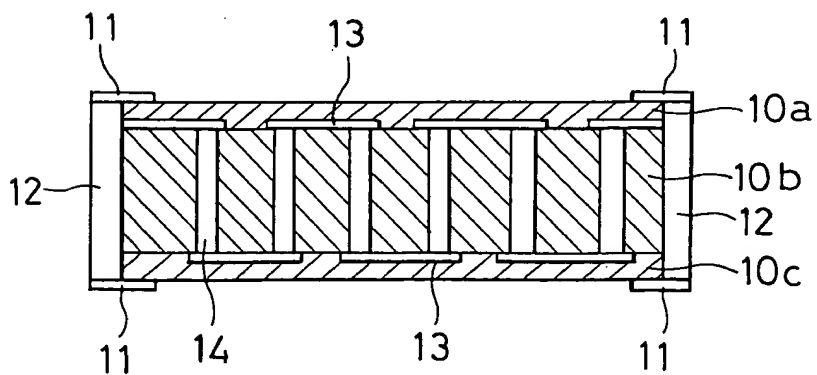


FIG. 16

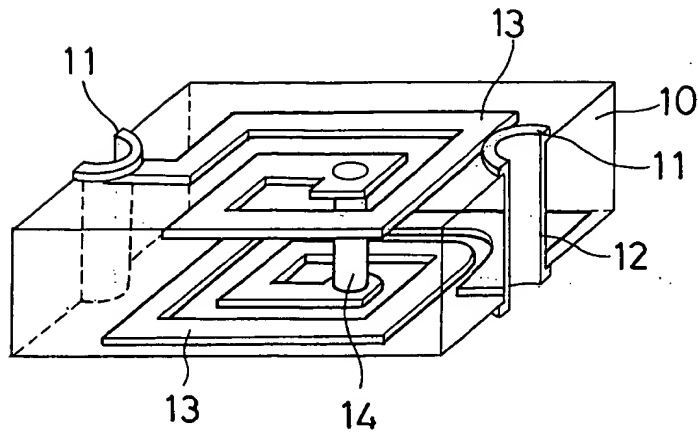
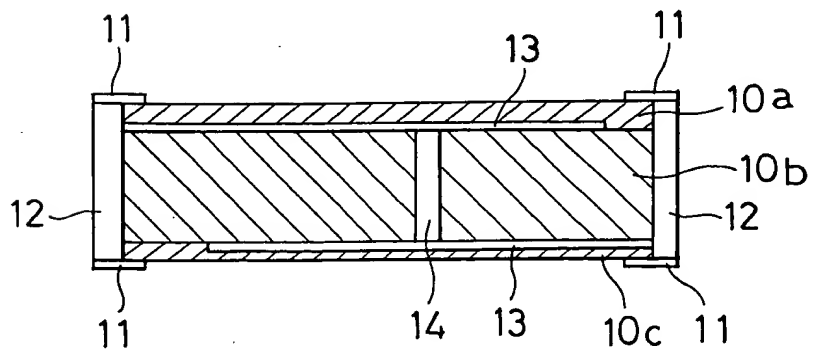


FIG. 17



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FIG. 18

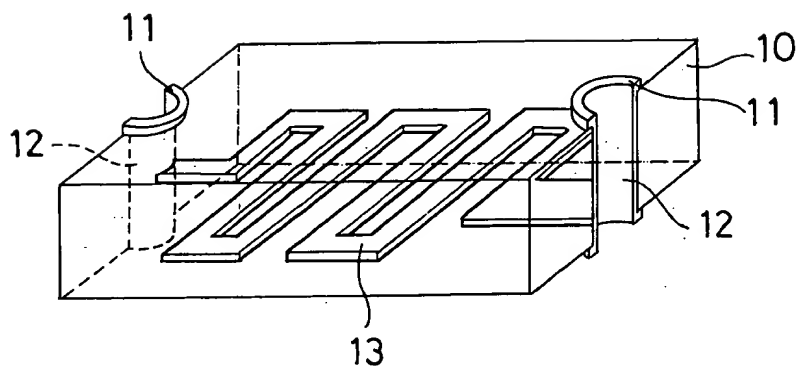
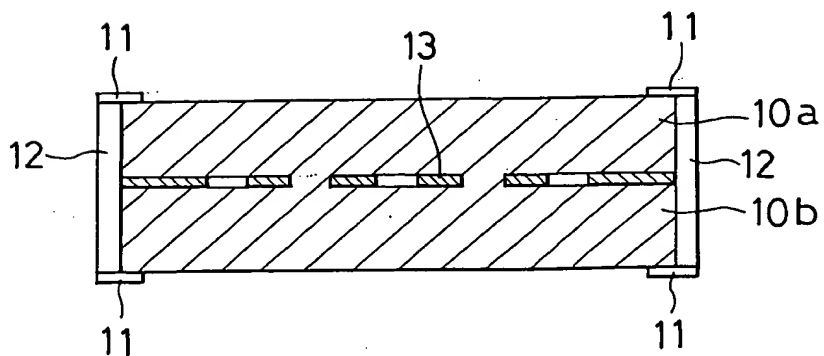


FIG. 19



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FIG. 20

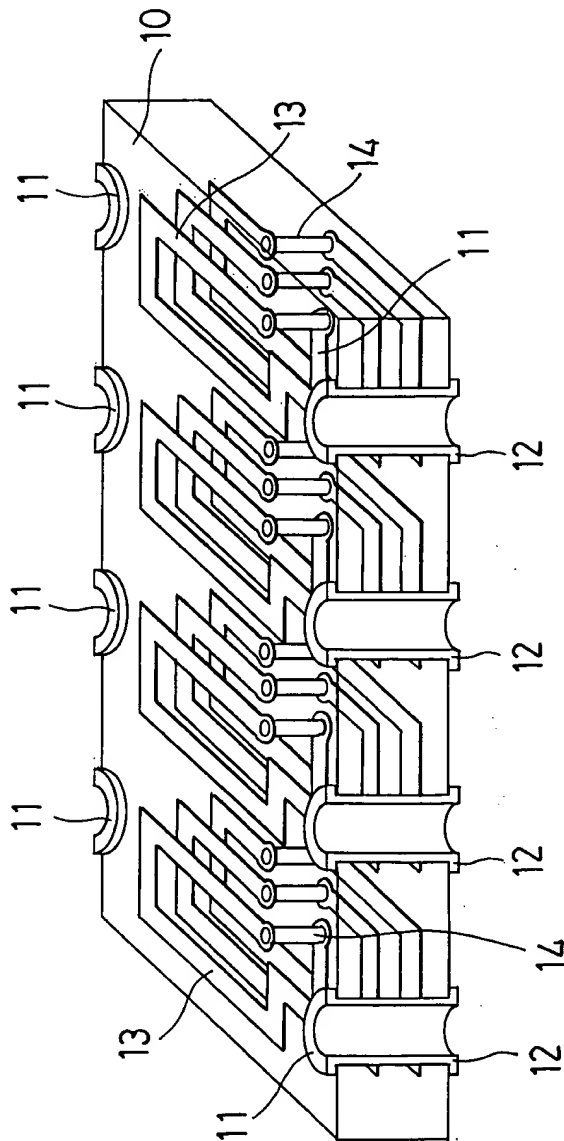


FIG. 21A

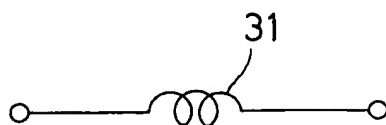


FIG. 21B

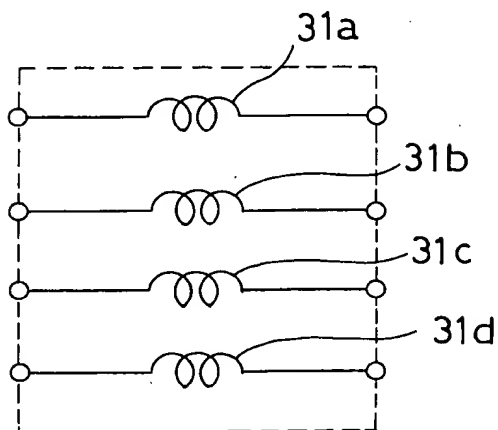
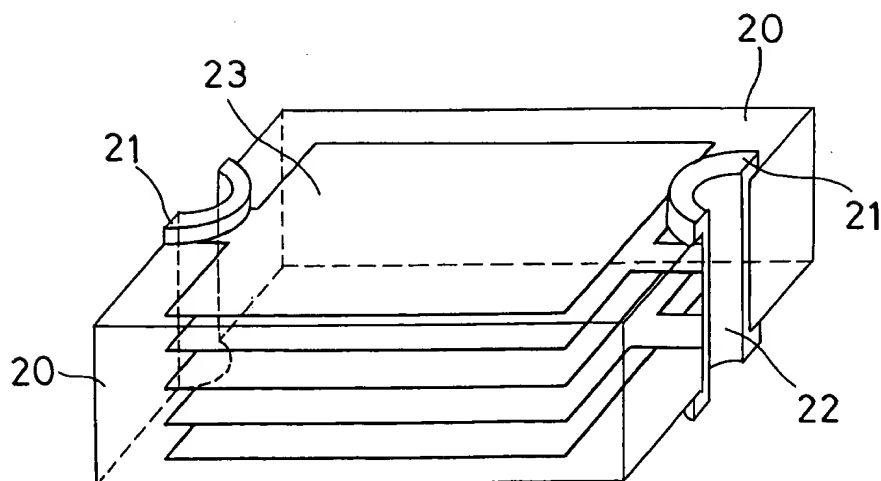
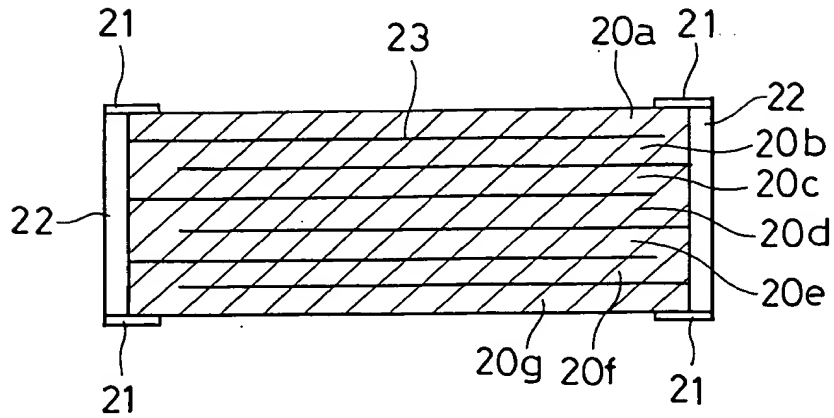


FIG. 22



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FIG. 23



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FIG. 24

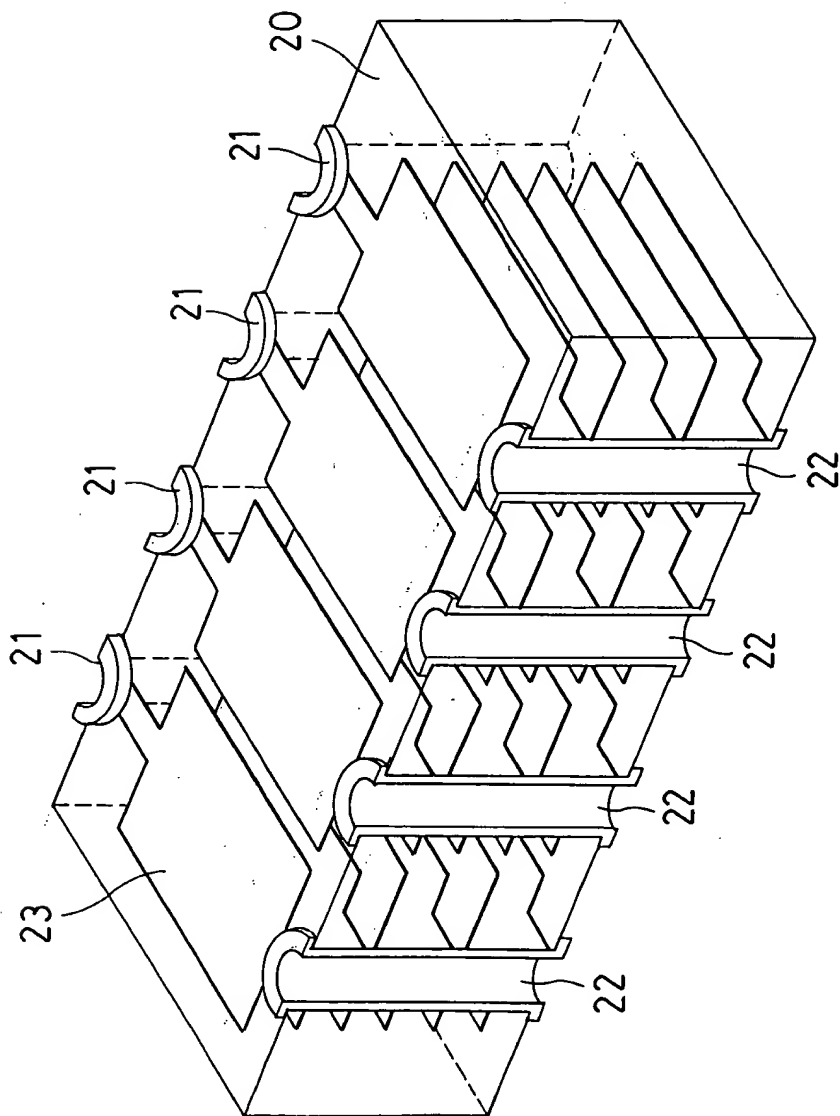


FIG. 25A

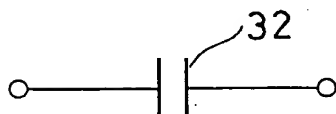


FIG. 25B

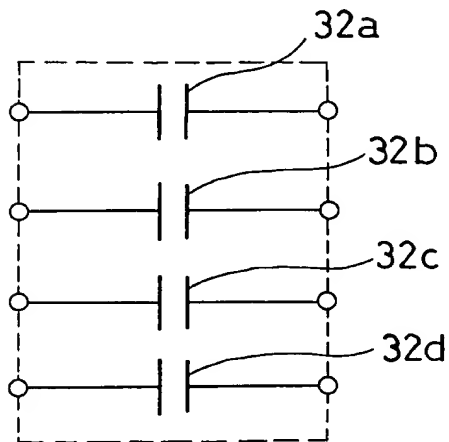


FIG. 26

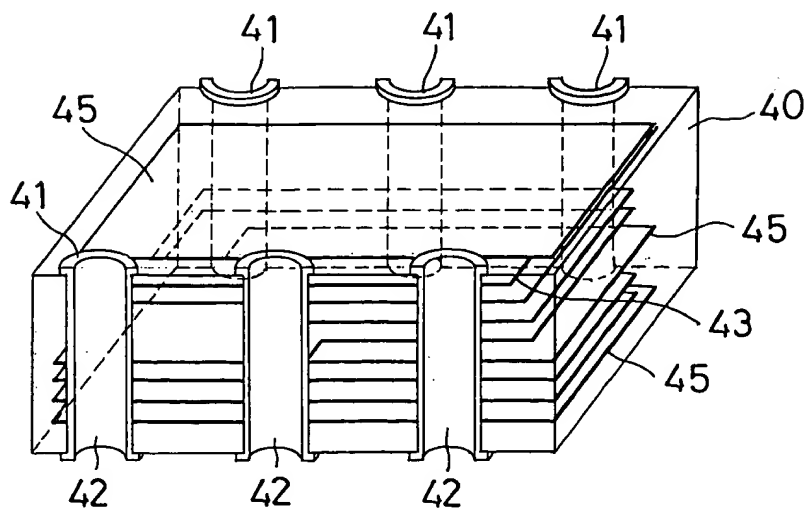
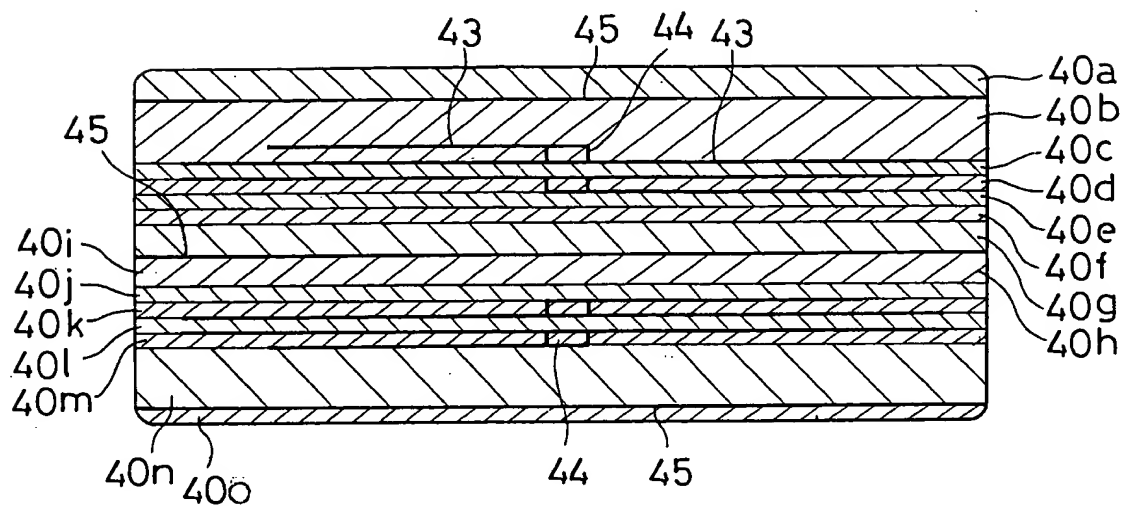
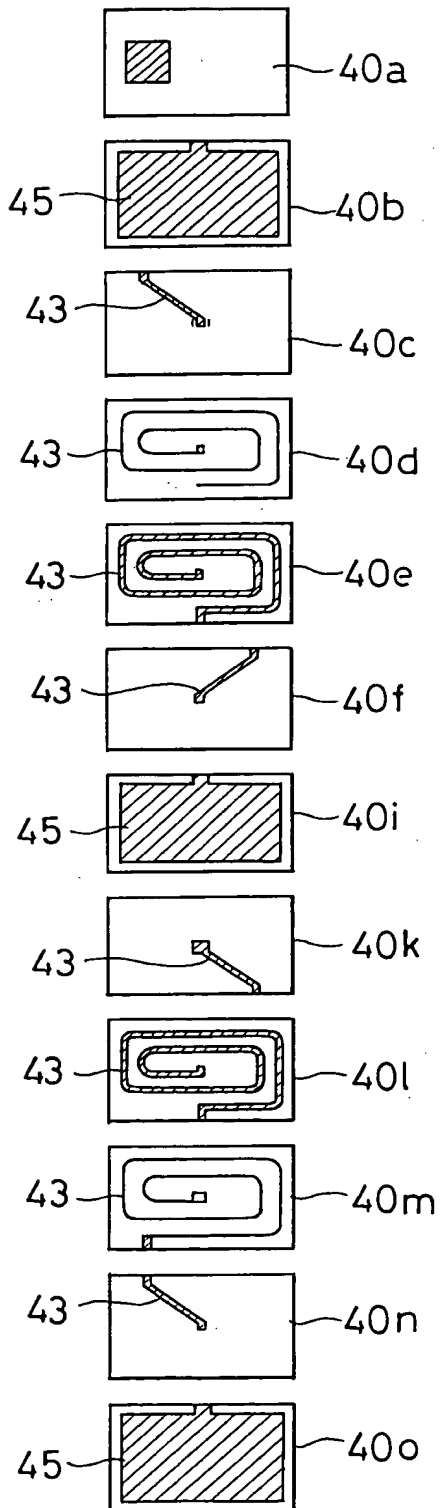


FIG. 27



008221" 00854260

FIG. 28



008221" 00864260

FIG. 29

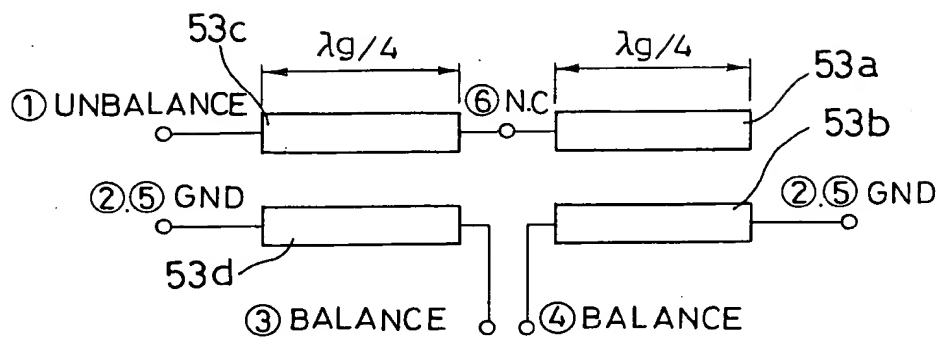
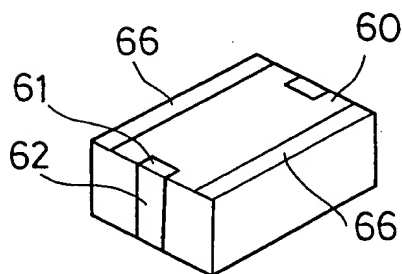
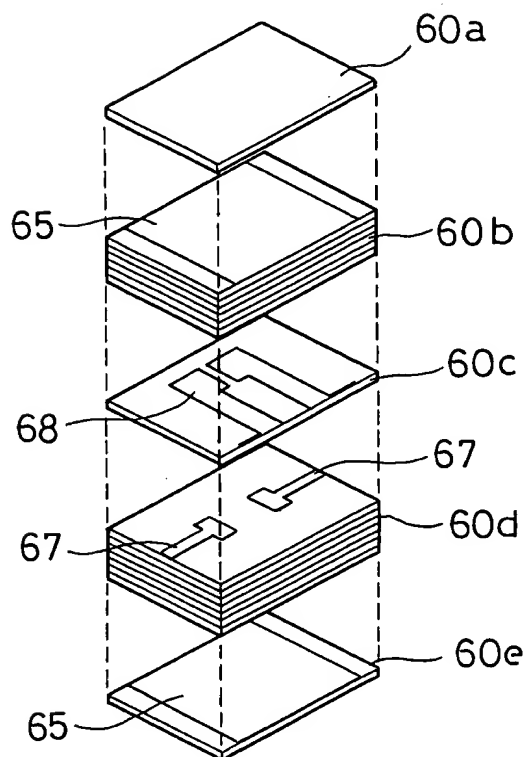


FIG. 30



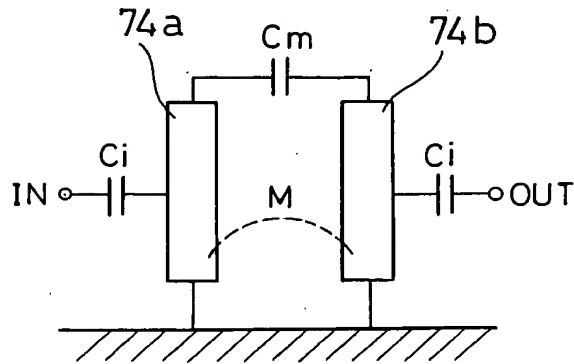
008221" 00864260

FIG. 31



09749800 122800 00822T 00864260

FIG. 32



00822T" 00364260

FIG. 33

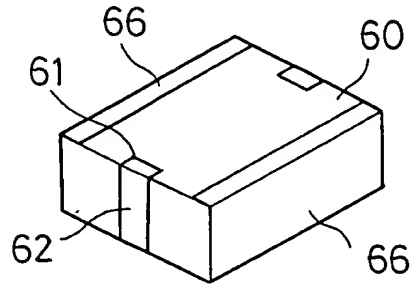
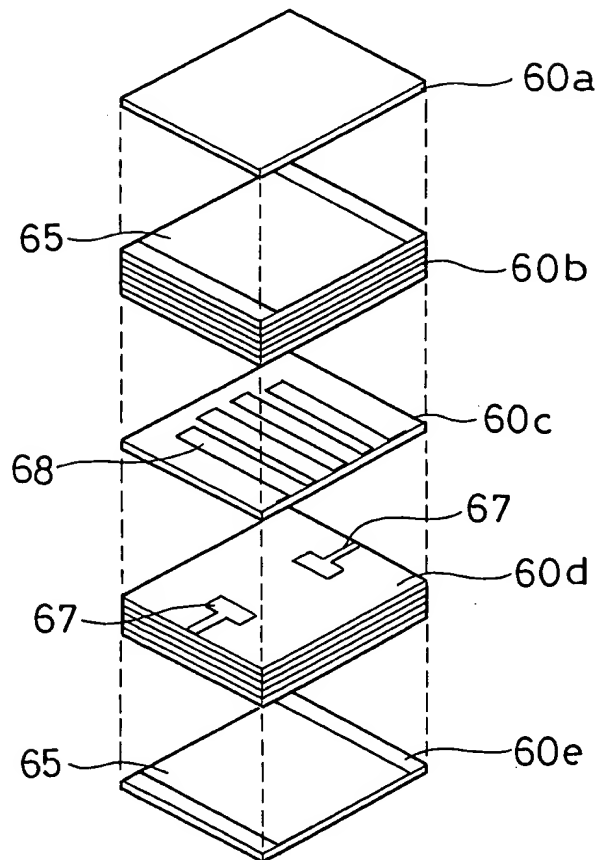
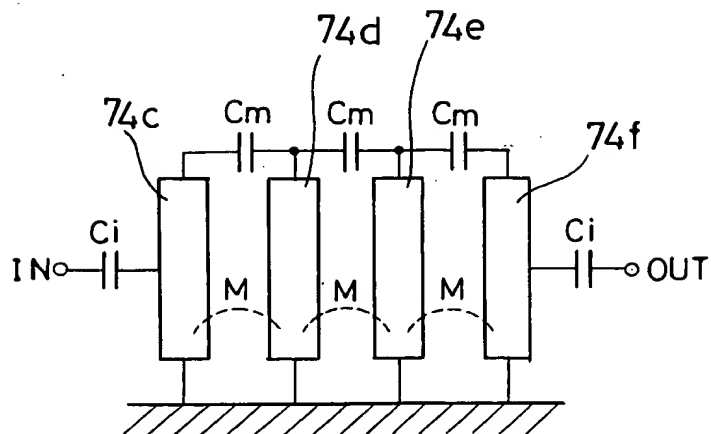


FIG. 34



09749800-122800

FIG. 35



09749800 122800

FIG. 36

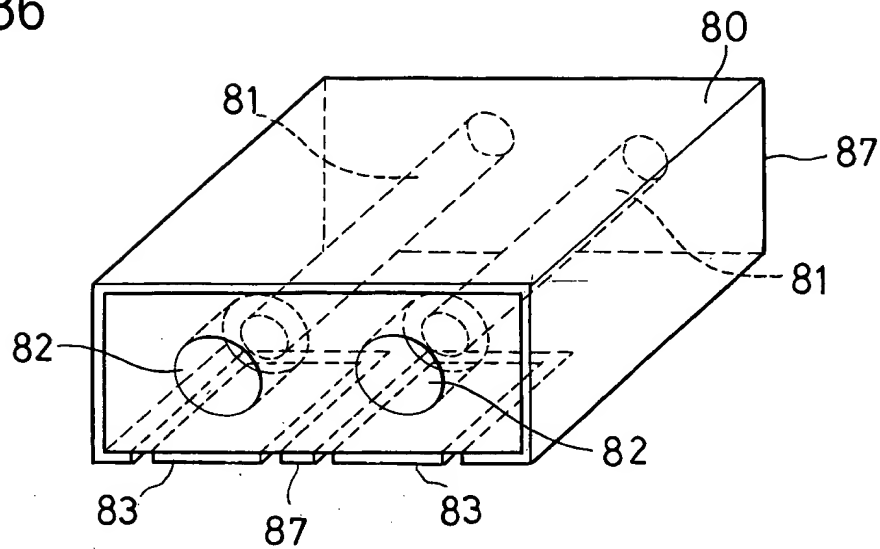


FIG. 37

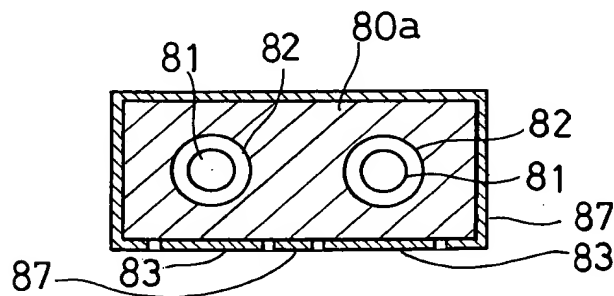


FIG. 38

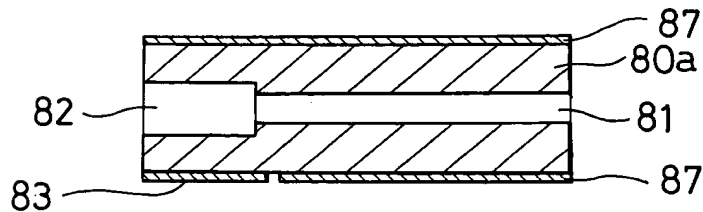


FIG. 39

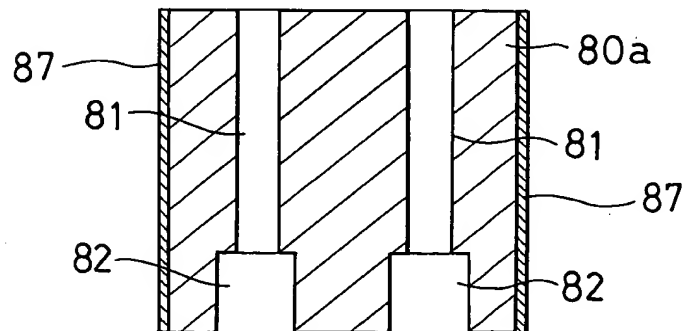


FIG. 40

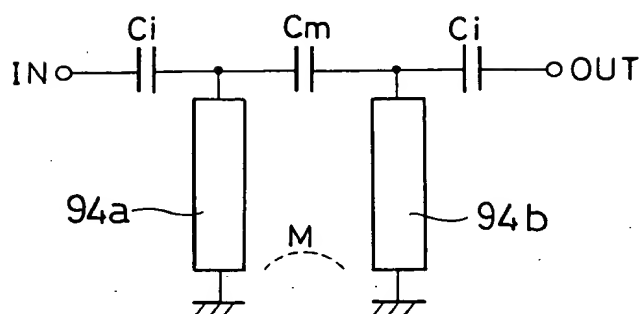


FIG. 41

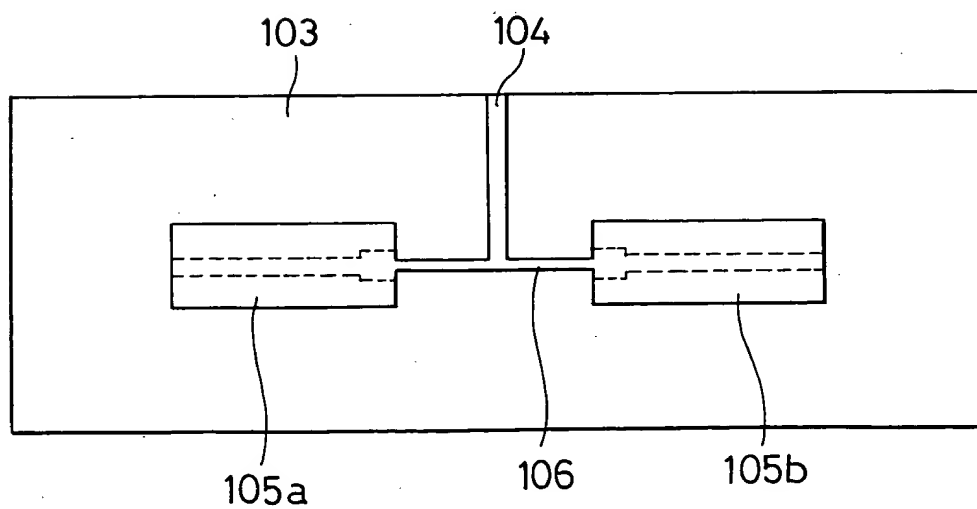


FIG. 42

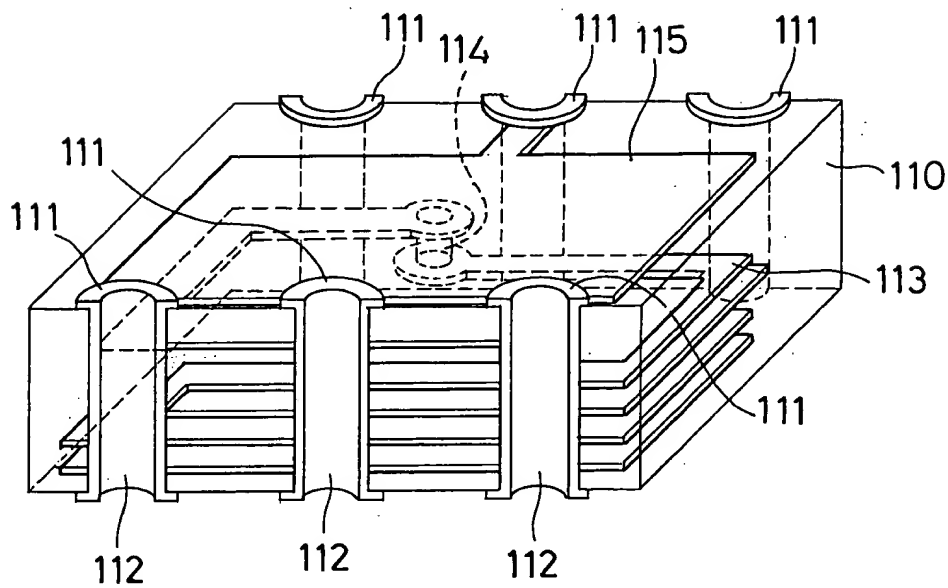


FIG. 43

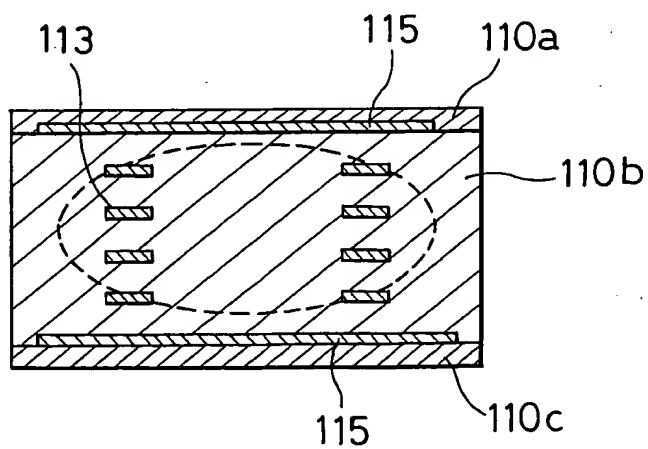
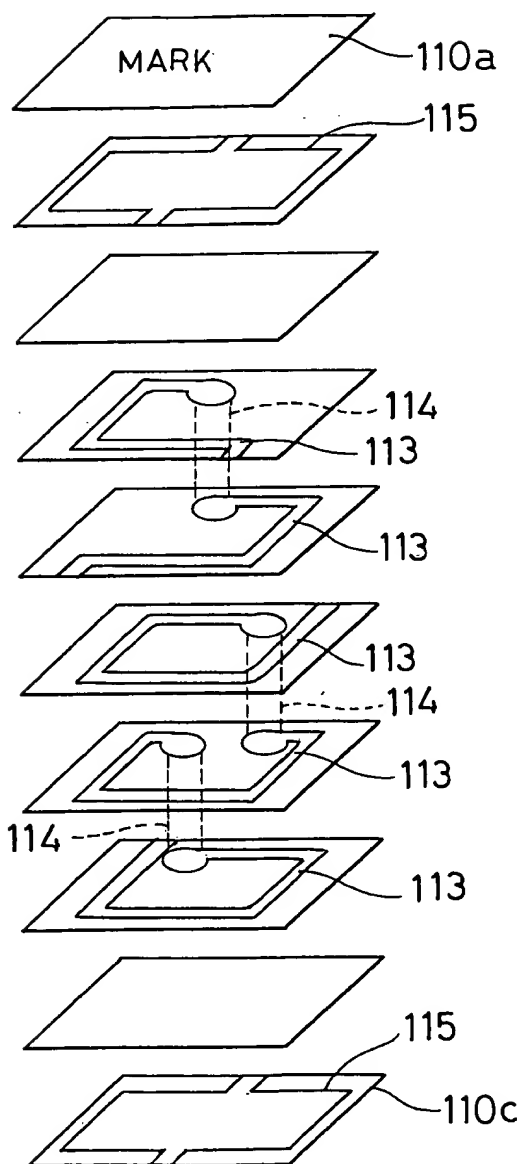


FIG. 44



008221" 00864260

FIG. 45

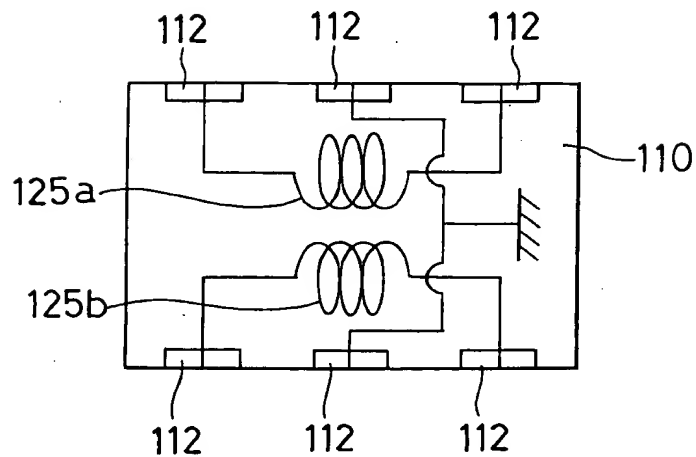
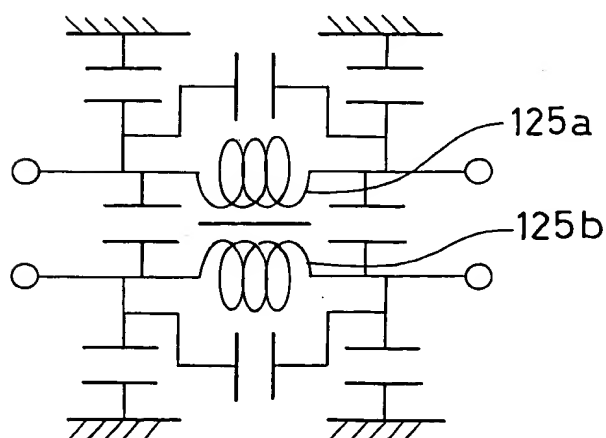


FIG. 46



00822T " 00864250

FIG. 47

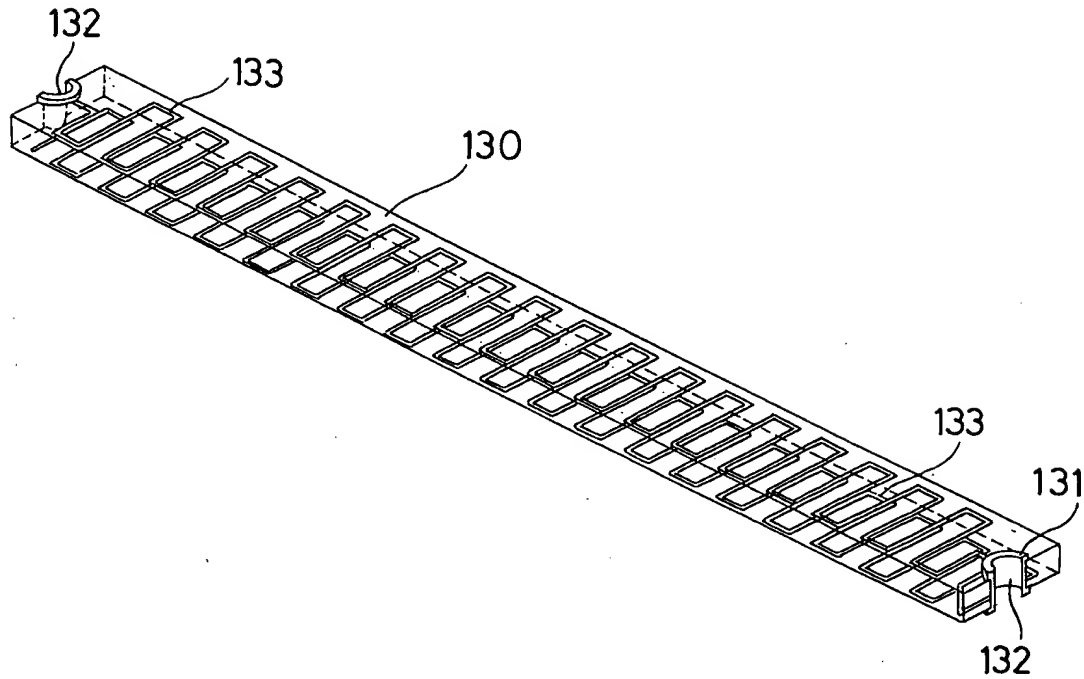


FIG. 48A

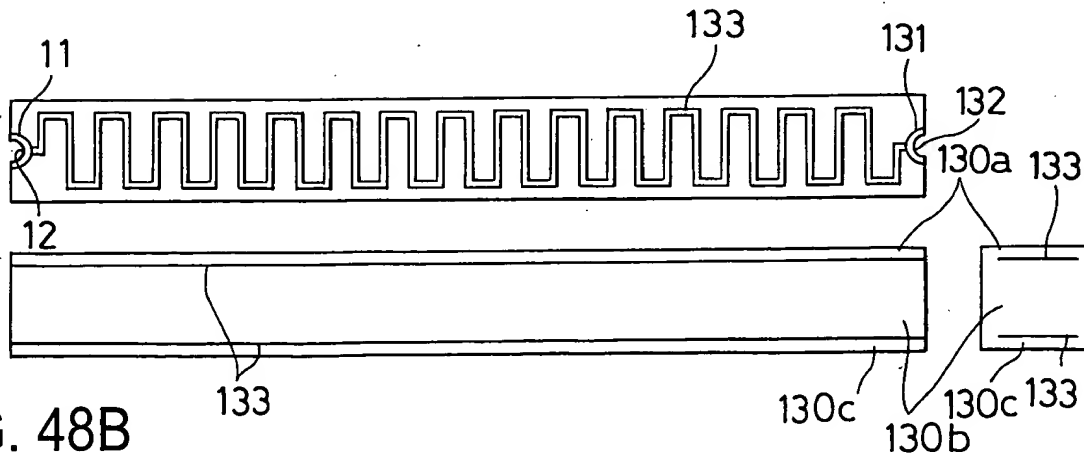
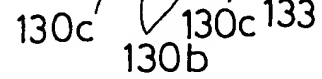


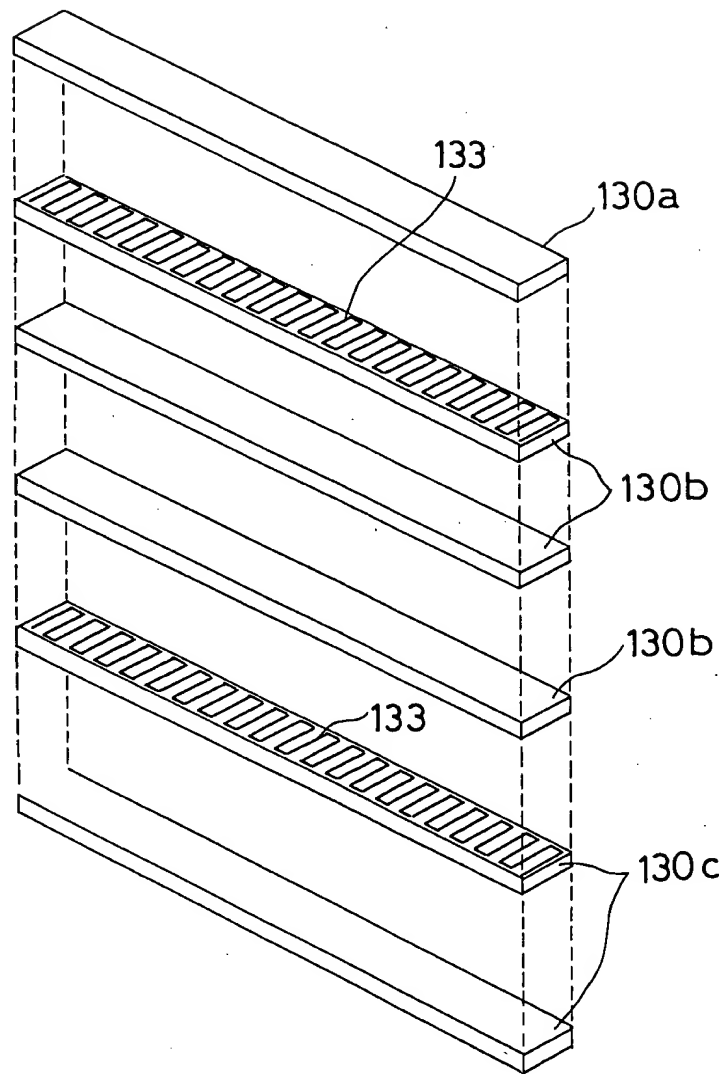
FIG. 48B

FIG. 48C



00822T 00864260

FIG. 49



008221 0086460

FIG. 50

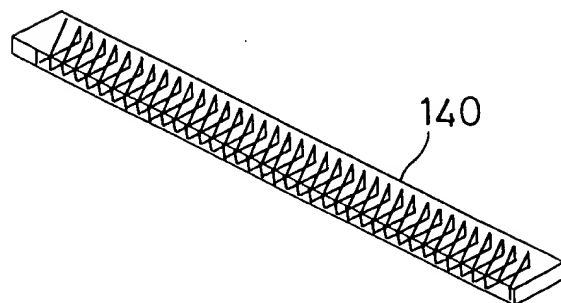
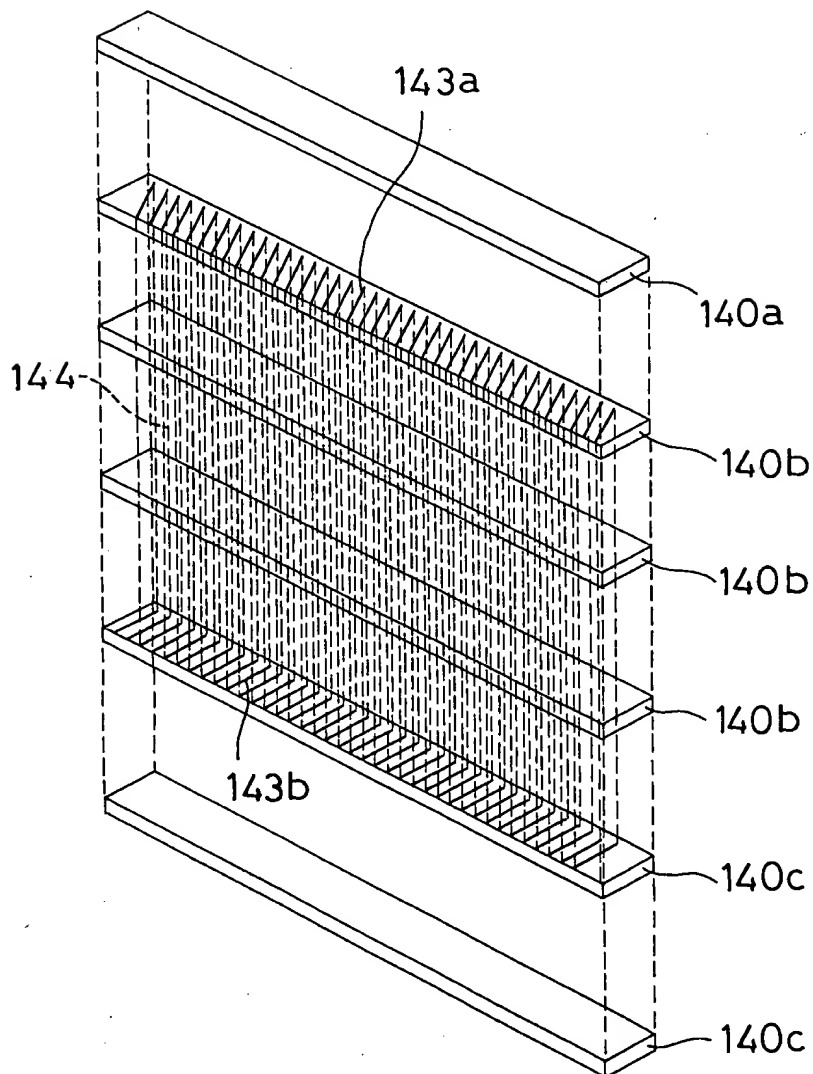


FIG. 51



008221 00854750

FIG. 52

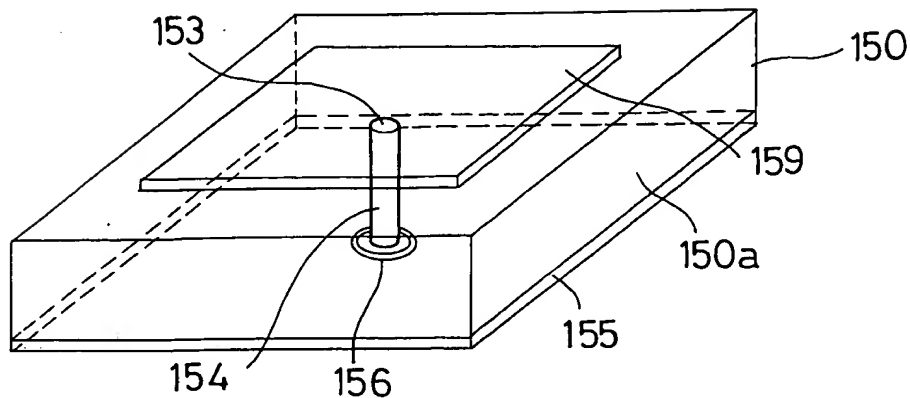


FIG. 53

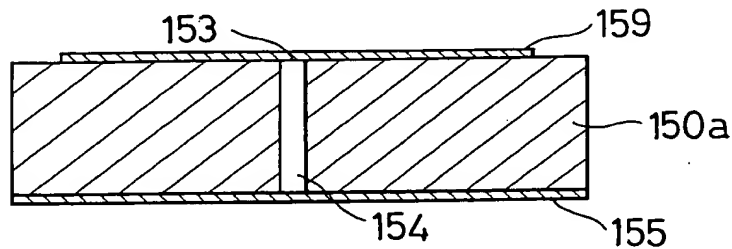


FIG. 54

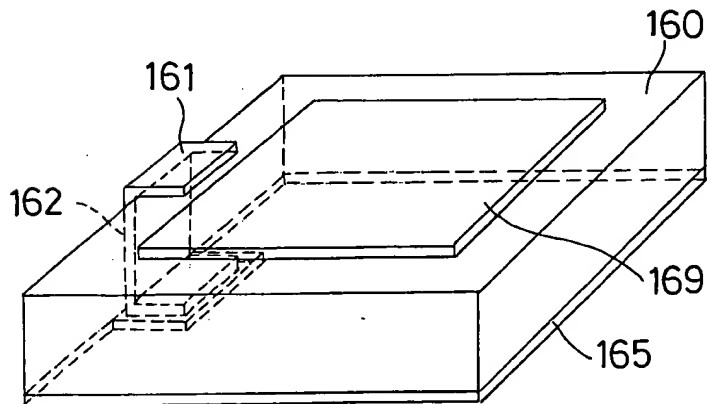
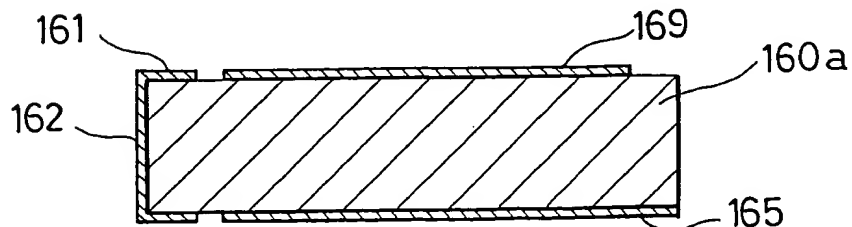


FIG. 55



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FIG. 56

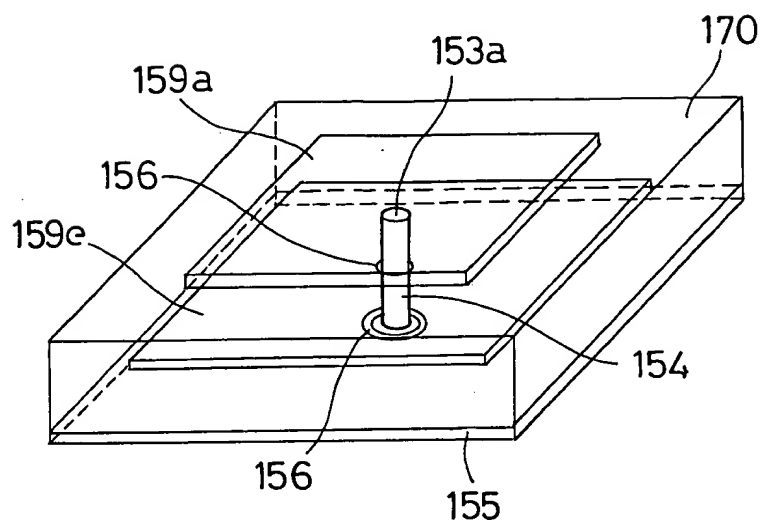


FIG. 57

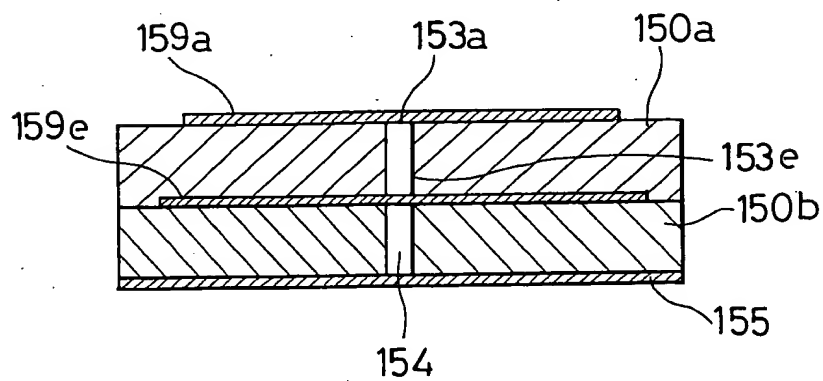


FIG. 58

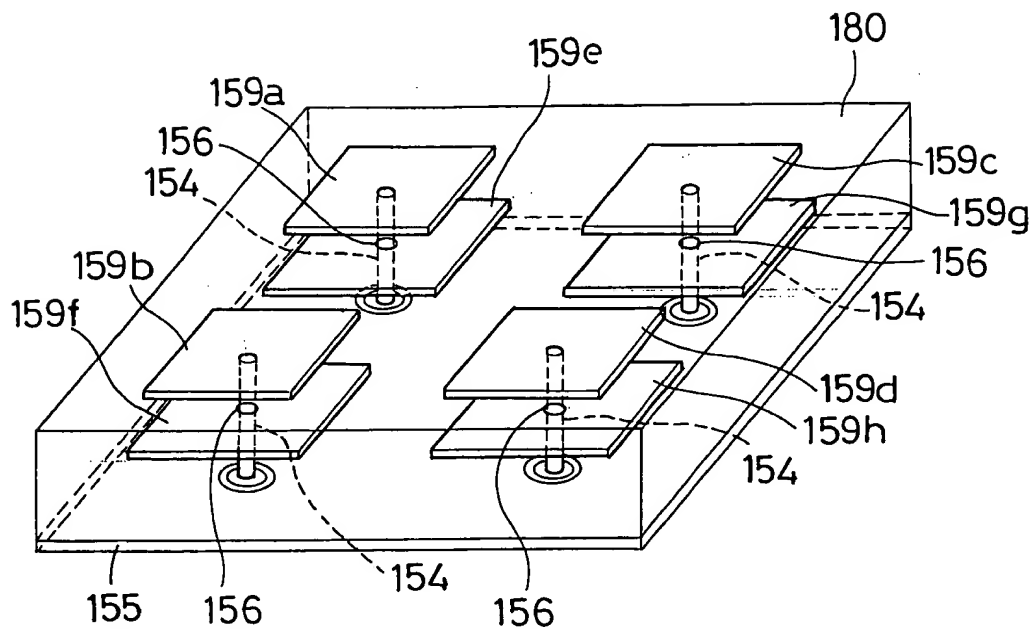


FIG. 59

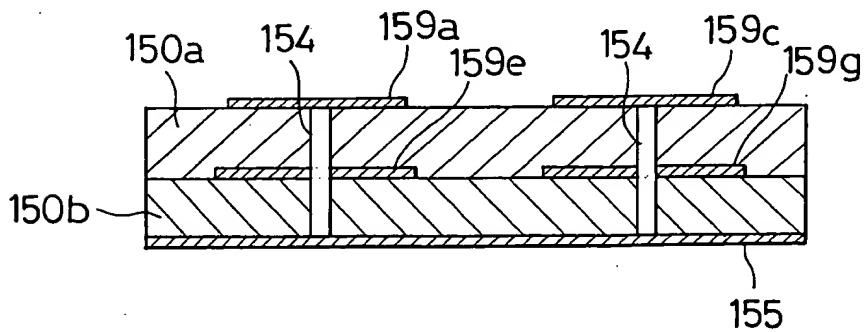


FIG. 60

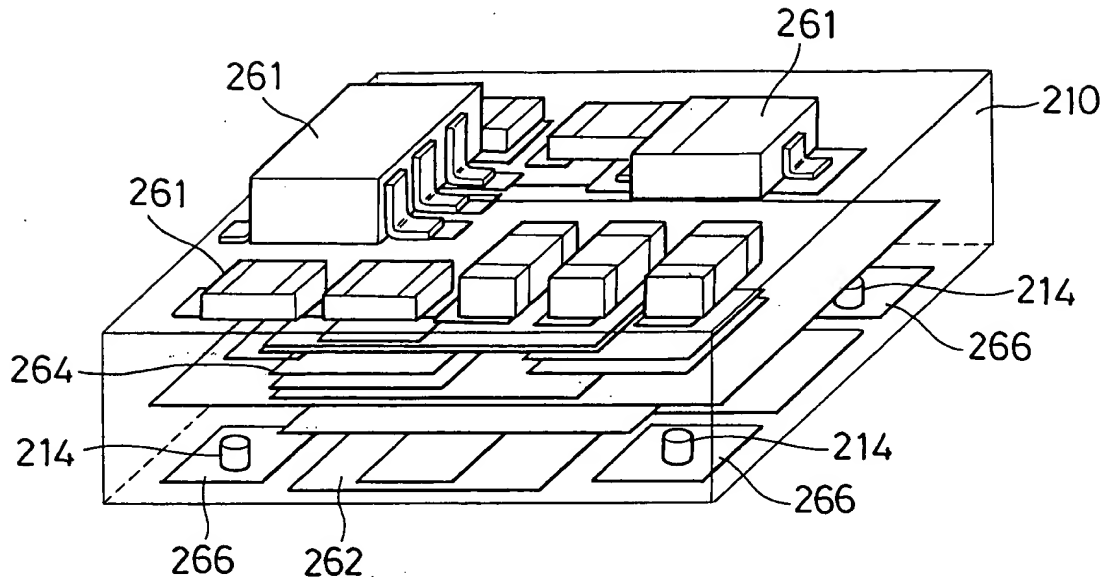


FIG. 61

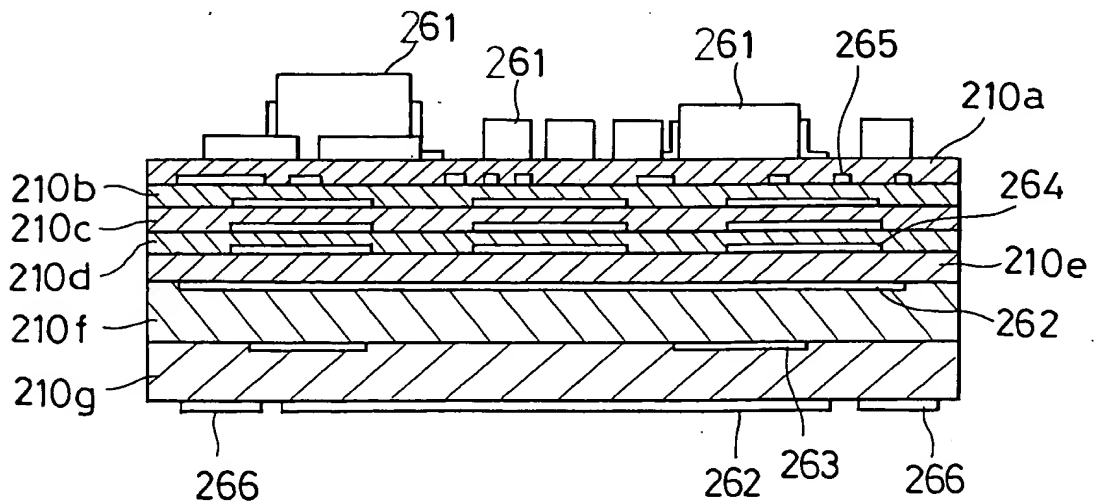
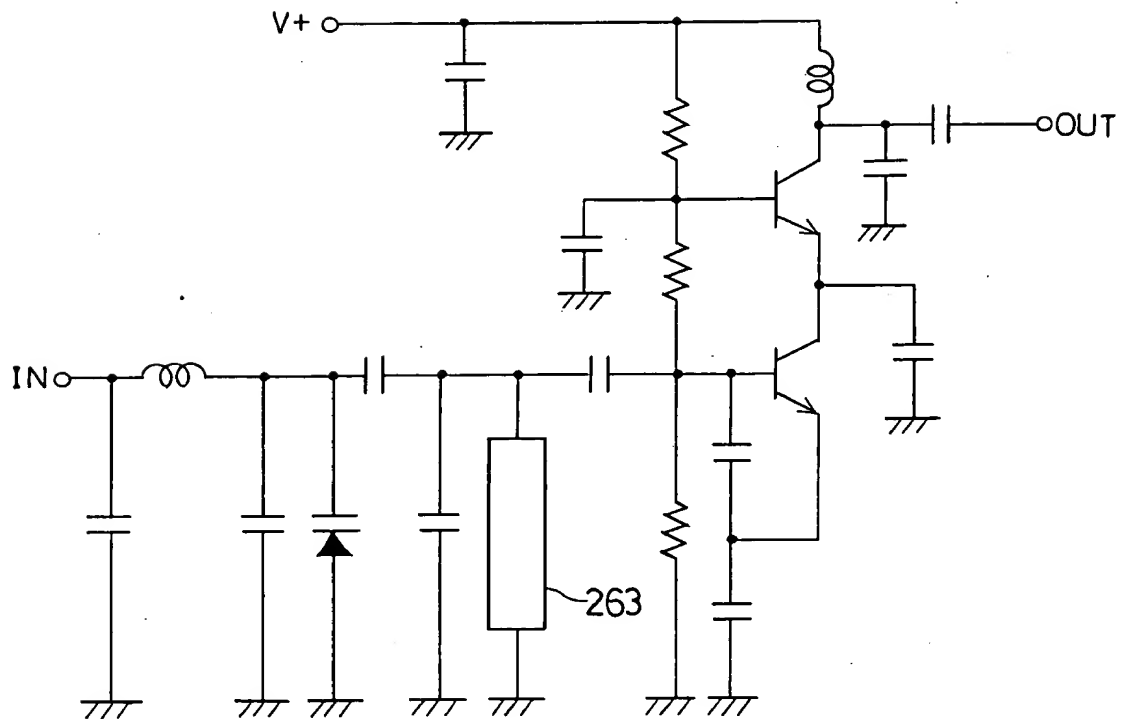
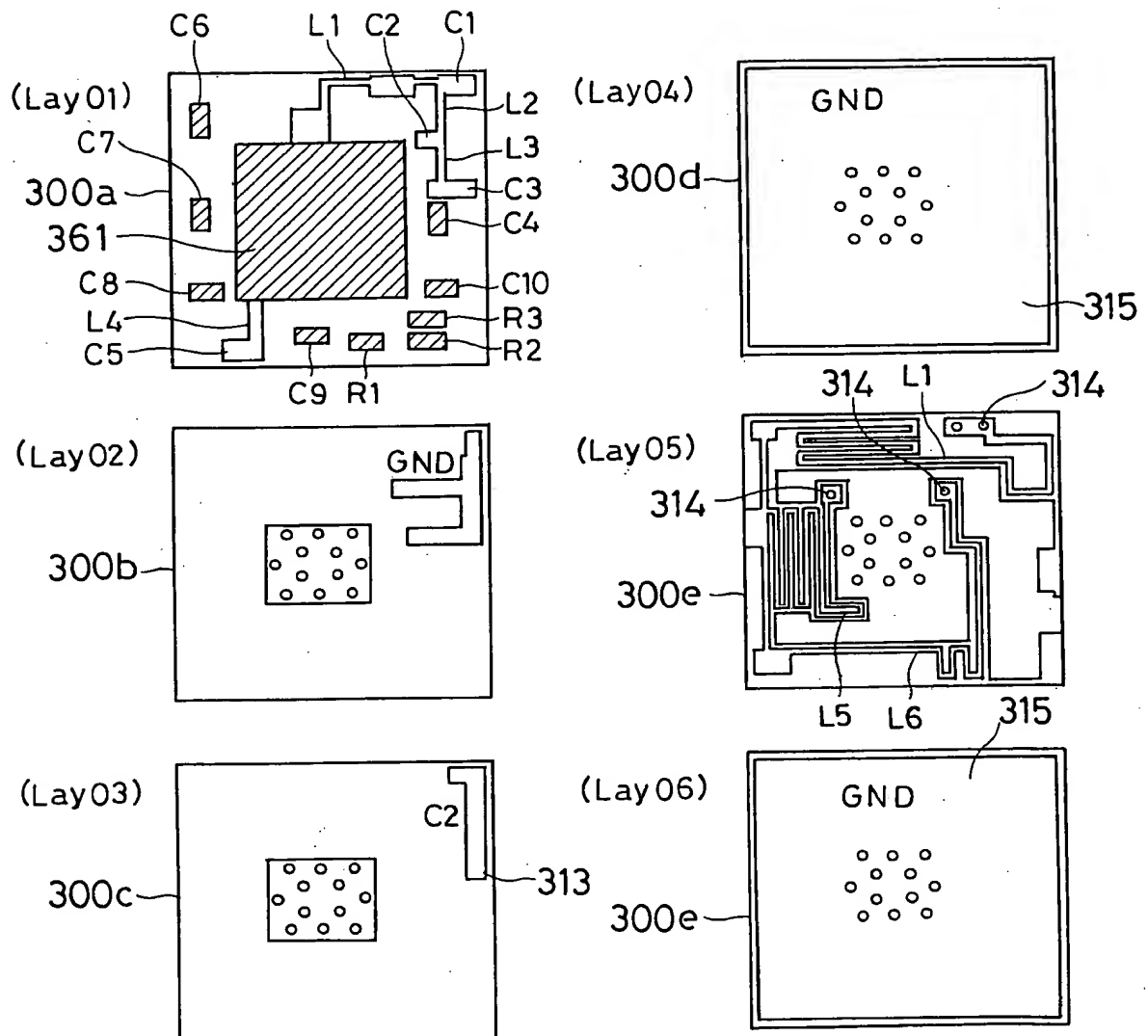


FIG. 62



003221" 00864/60

FIG. 63



00822T"00864260

FIG. 64

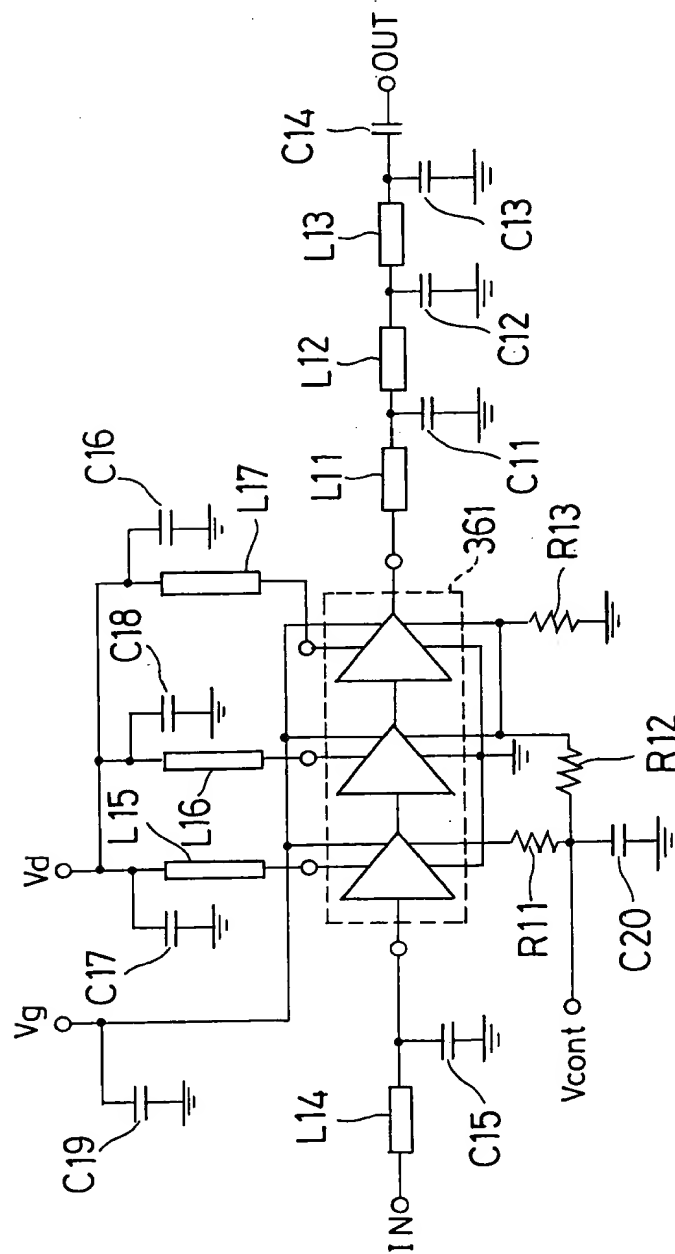


FIG. 65

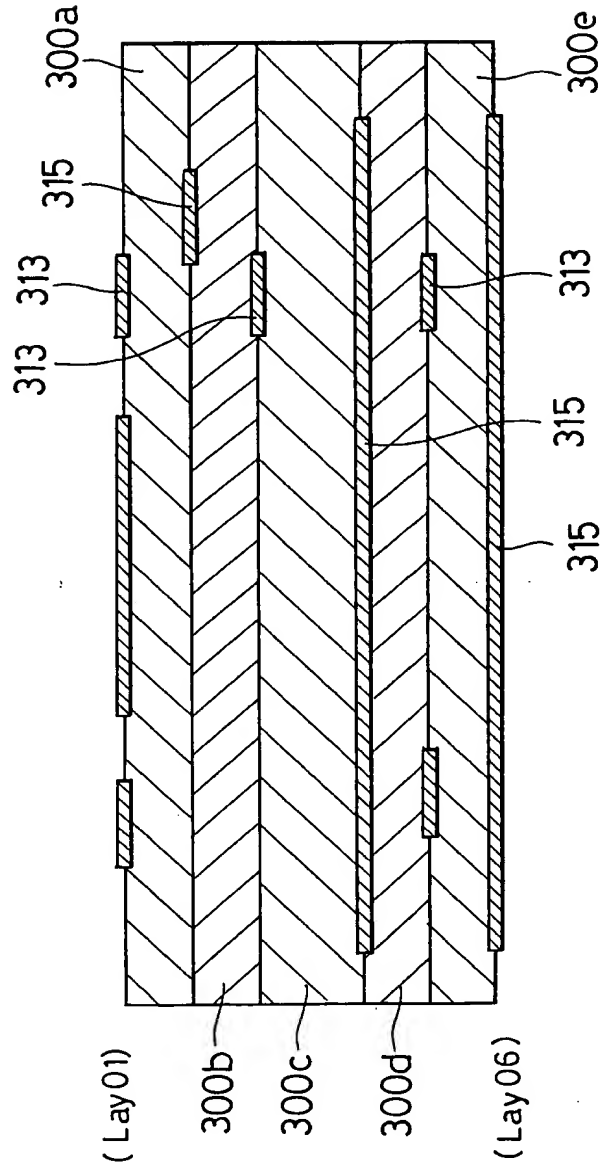
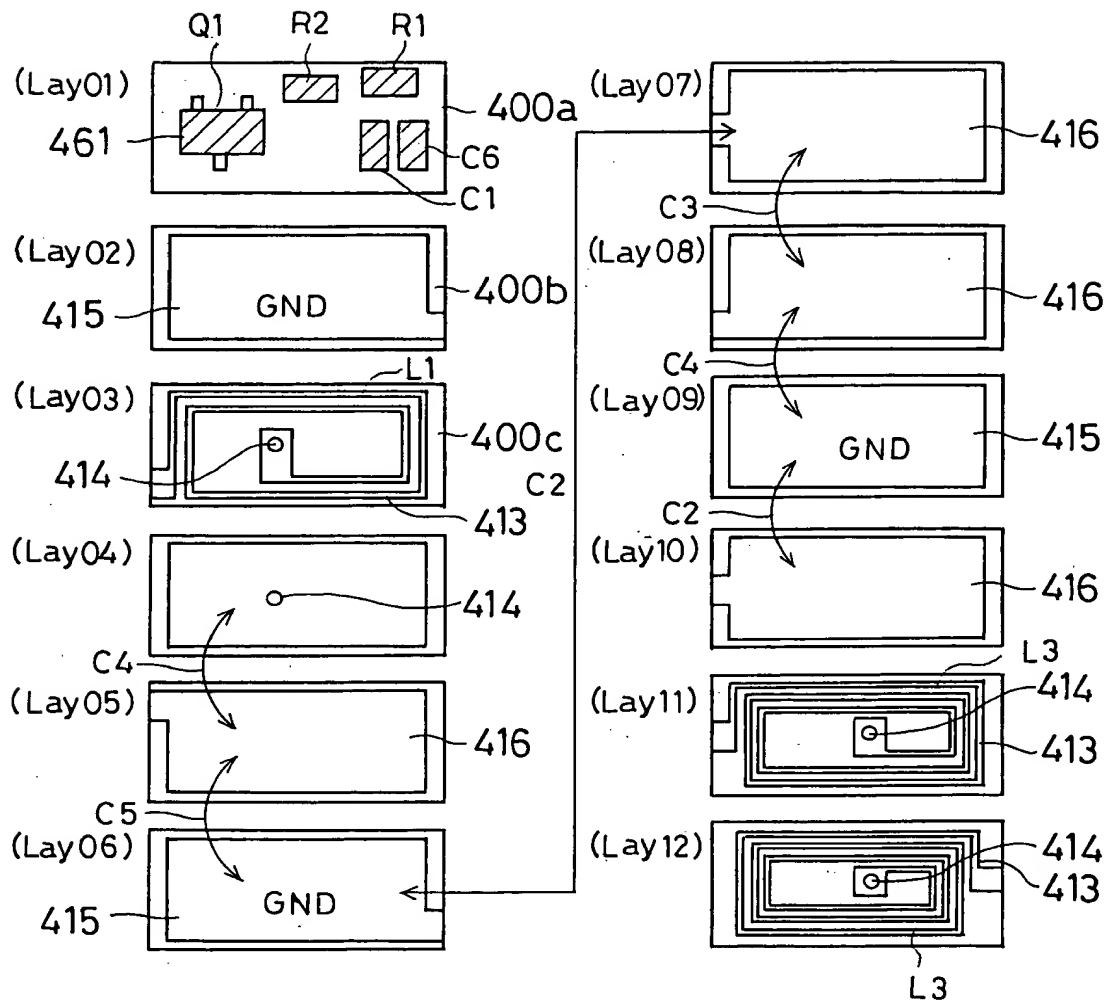


FIG. 66



003221" 00364260

FIG. 67

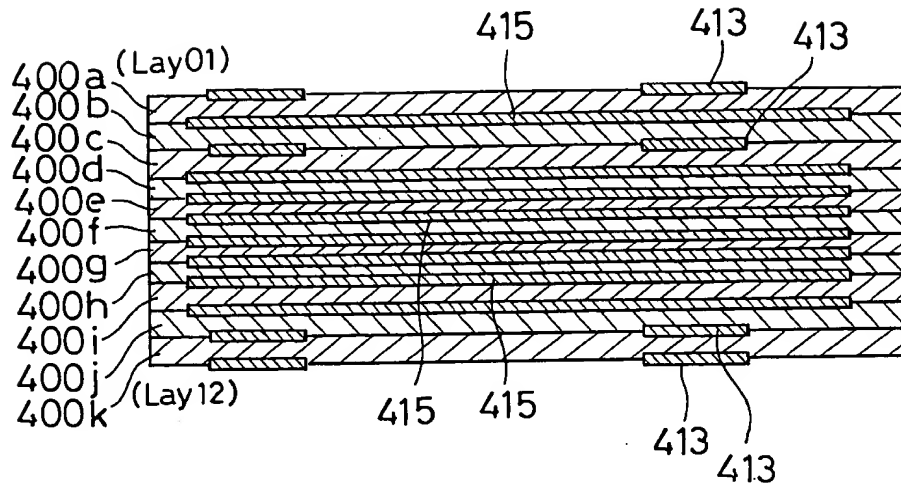
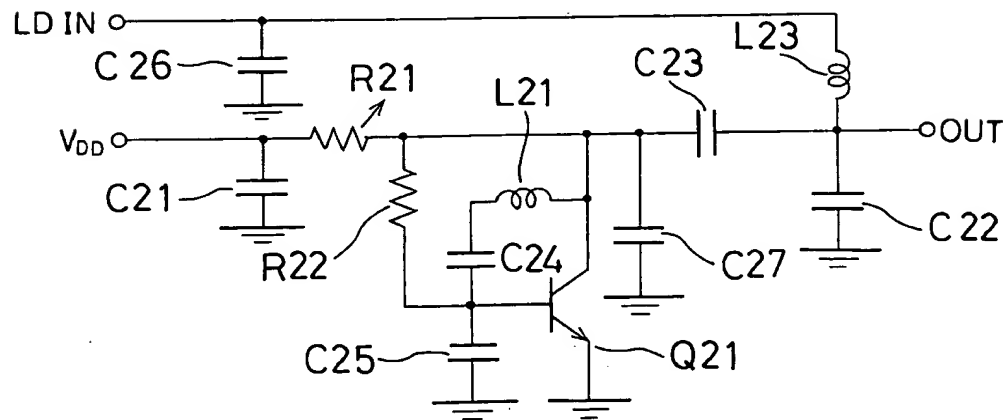
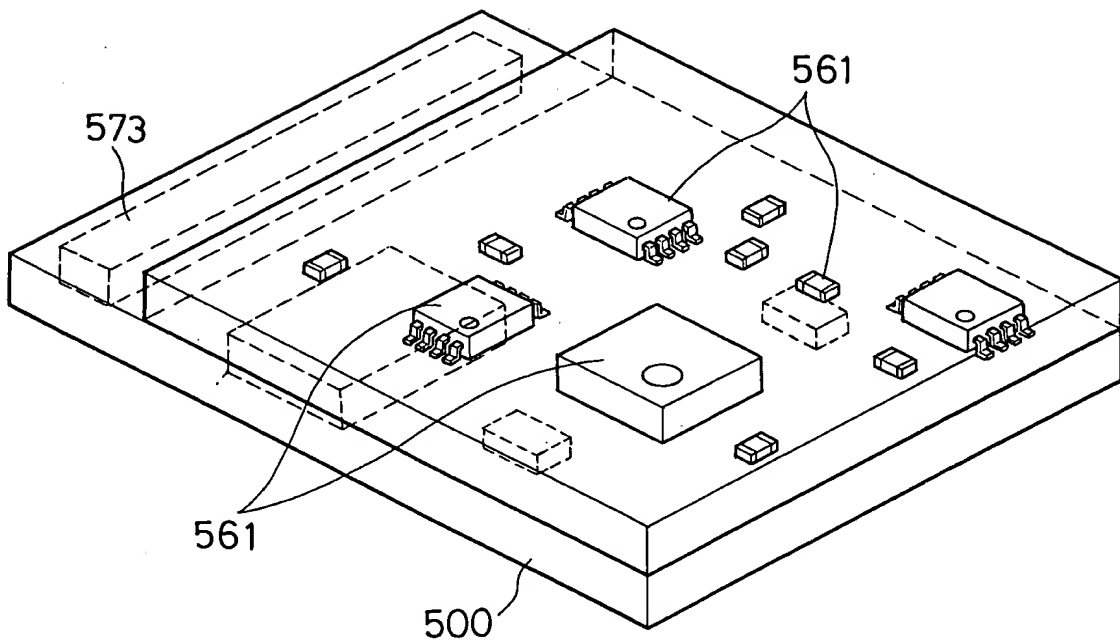


FIG. 68



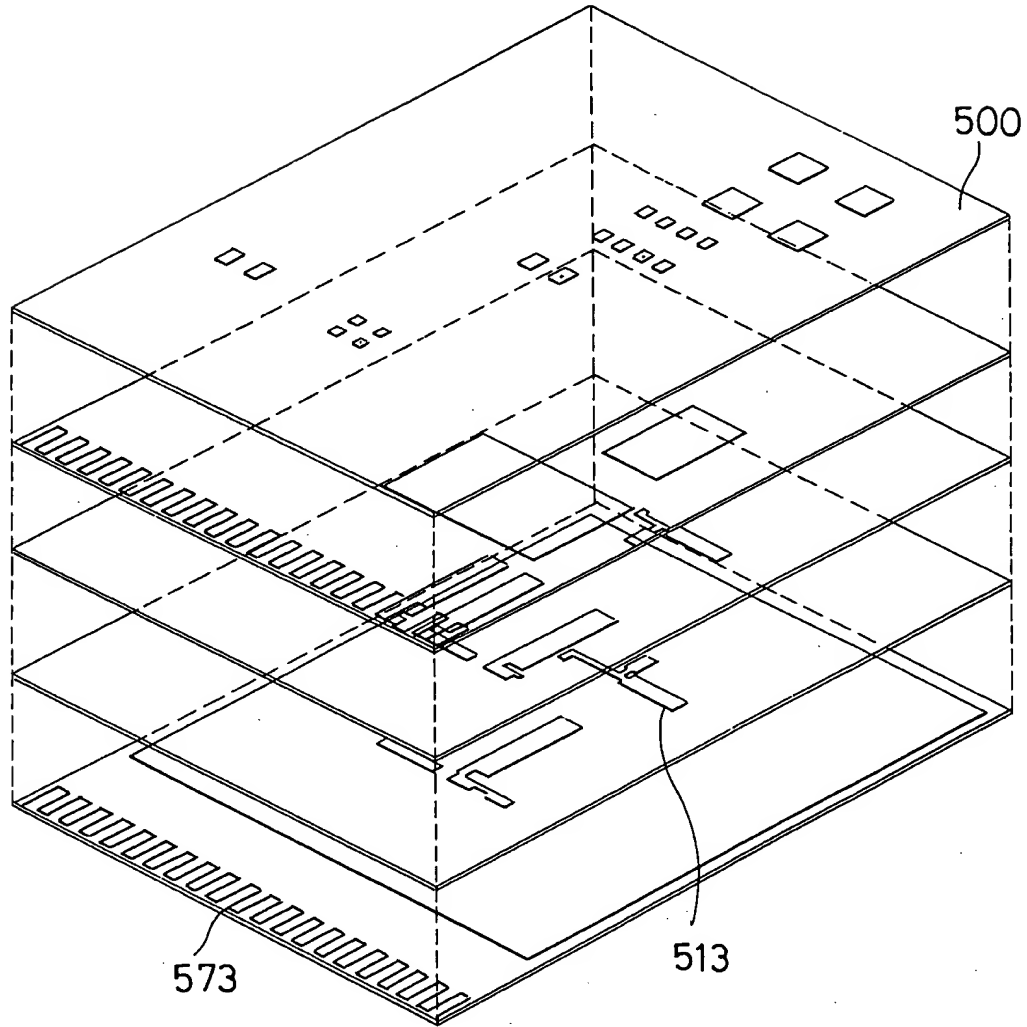
008221-00864260

FIG. 69



008221" 00864260

FIG. 71



008221" 00864260

FIG. 72

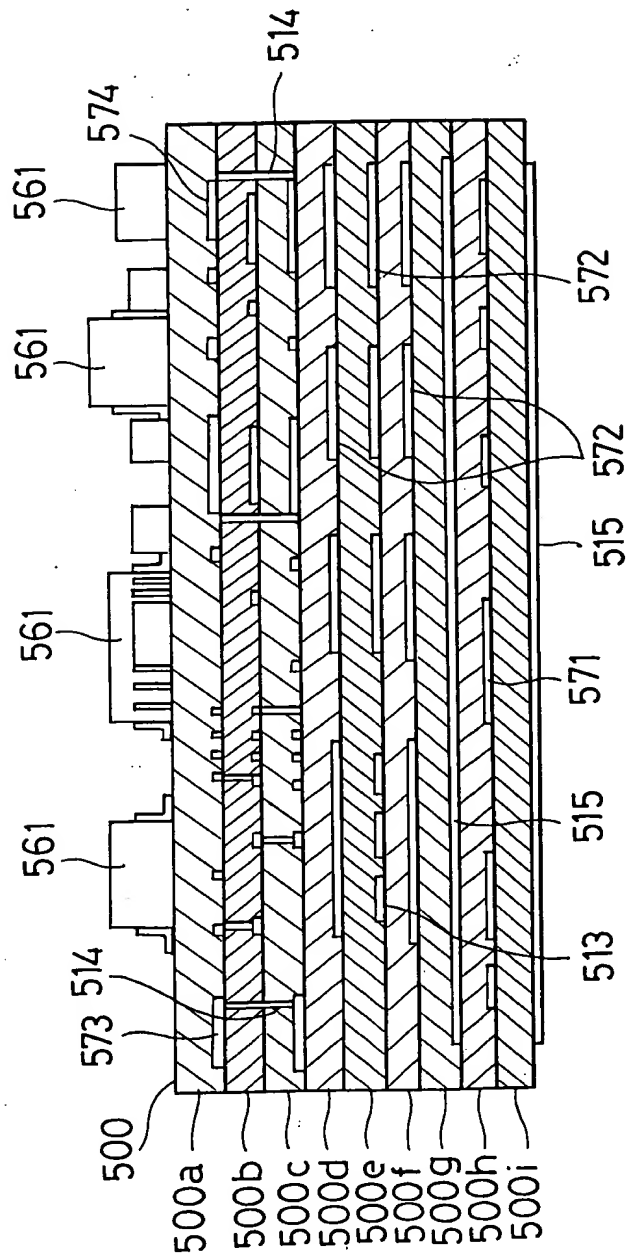


FIG. 73

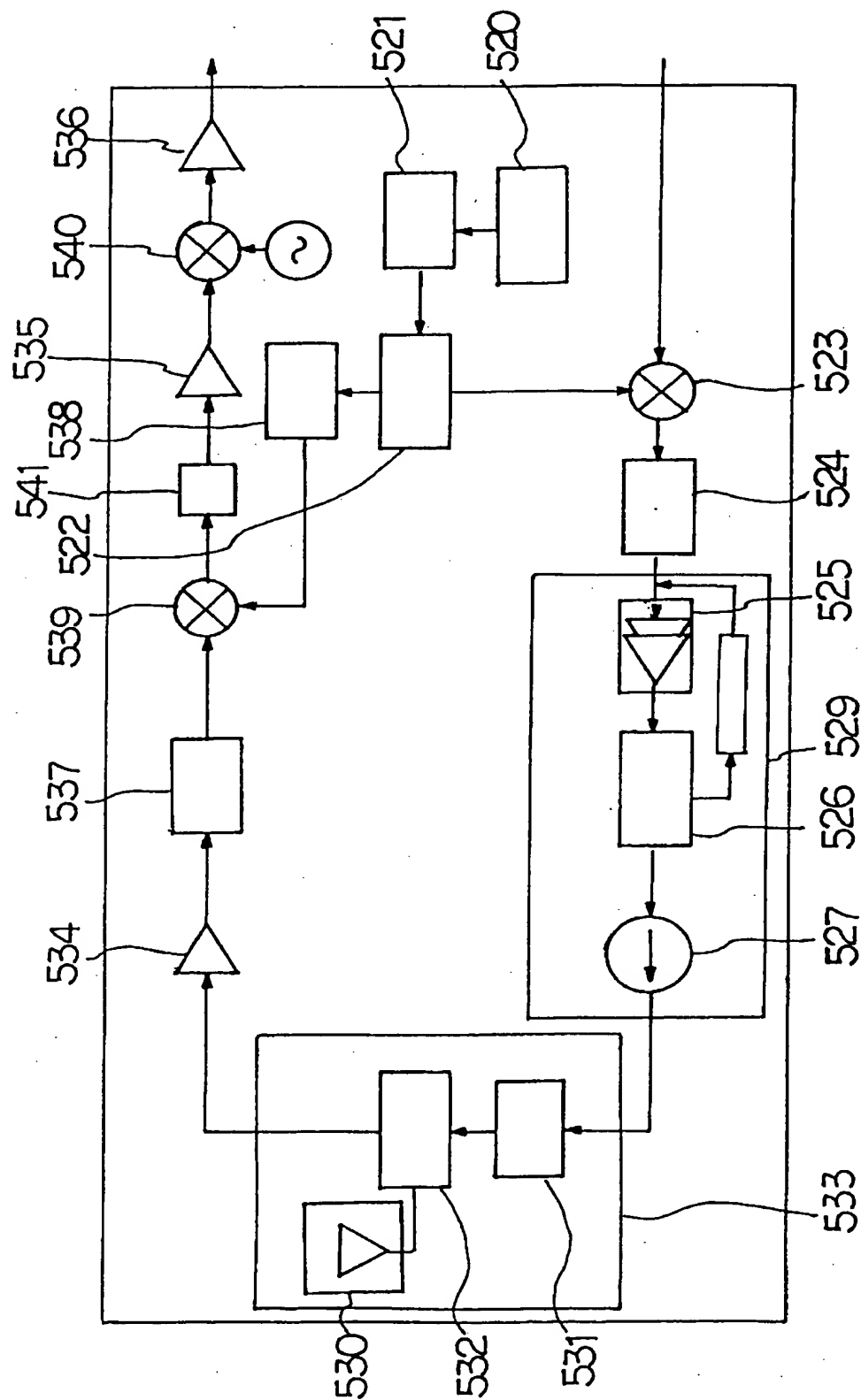


FIG. 74

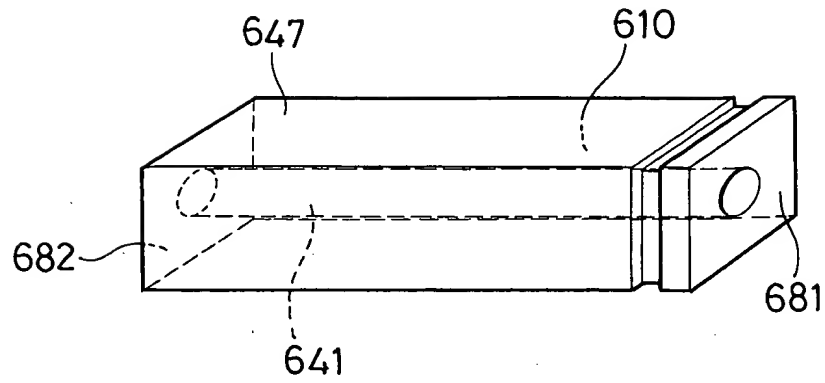
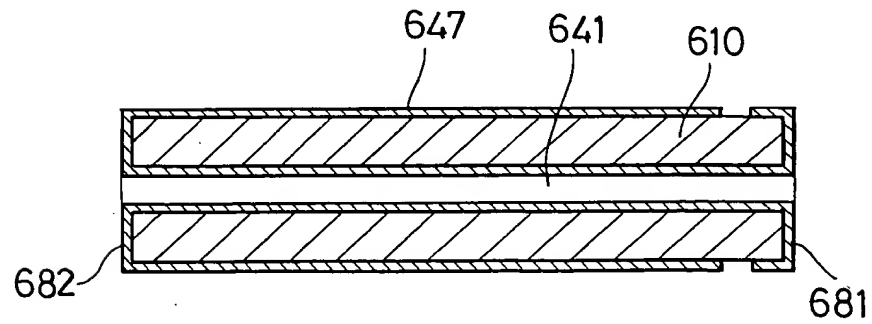


FIG. 75



00822T 0086460

FIG. 76

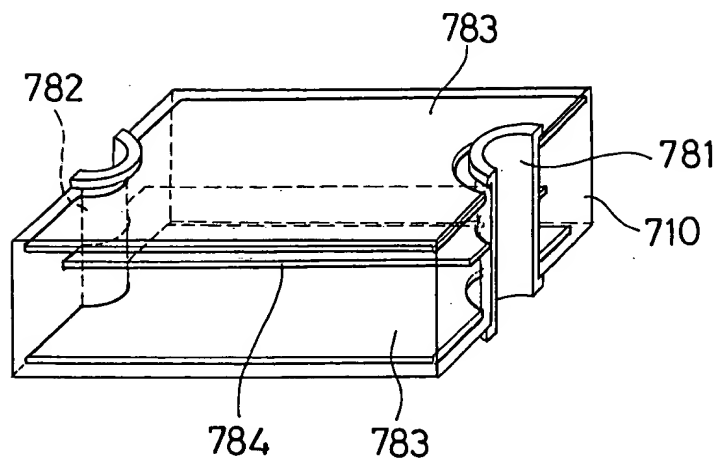
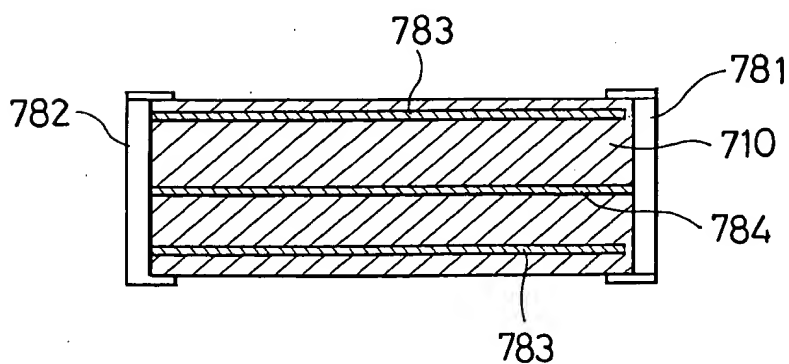


FIG. 77



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FIG. 78

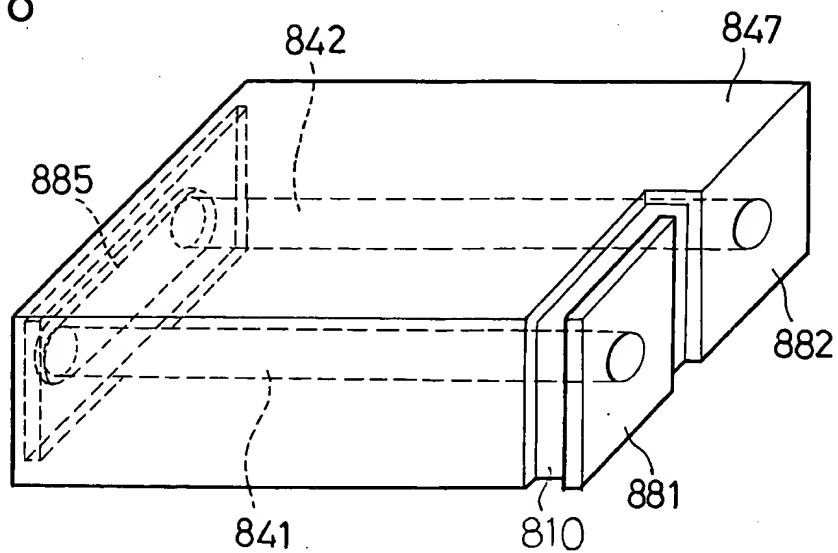


FIG. 79

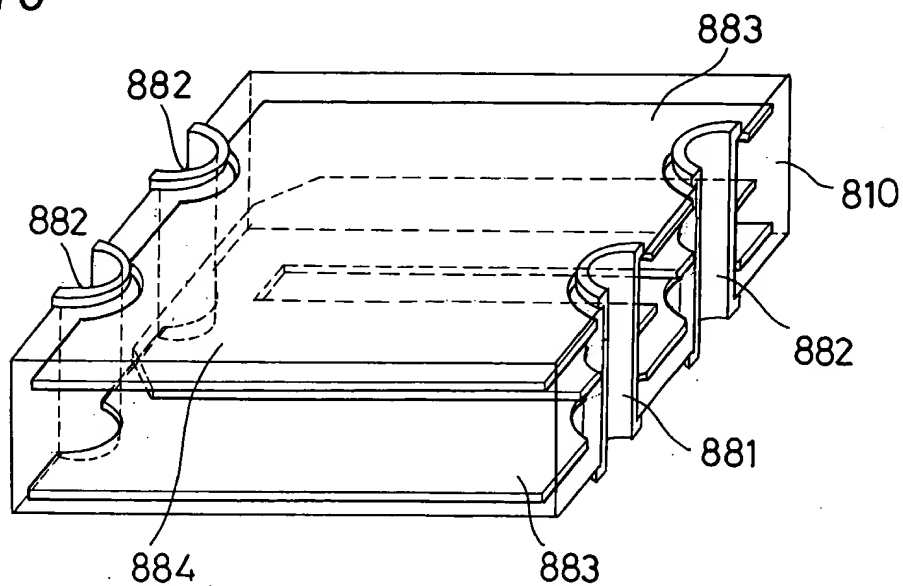


FIG. 80

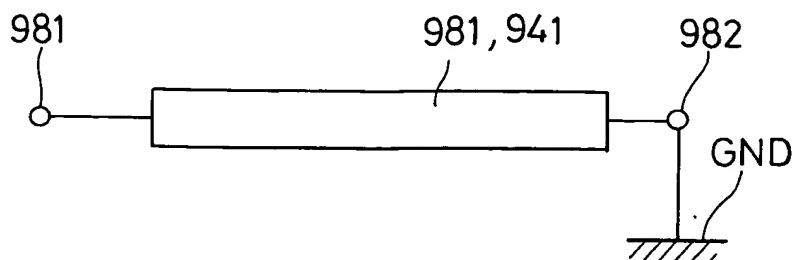


FIG. 81A

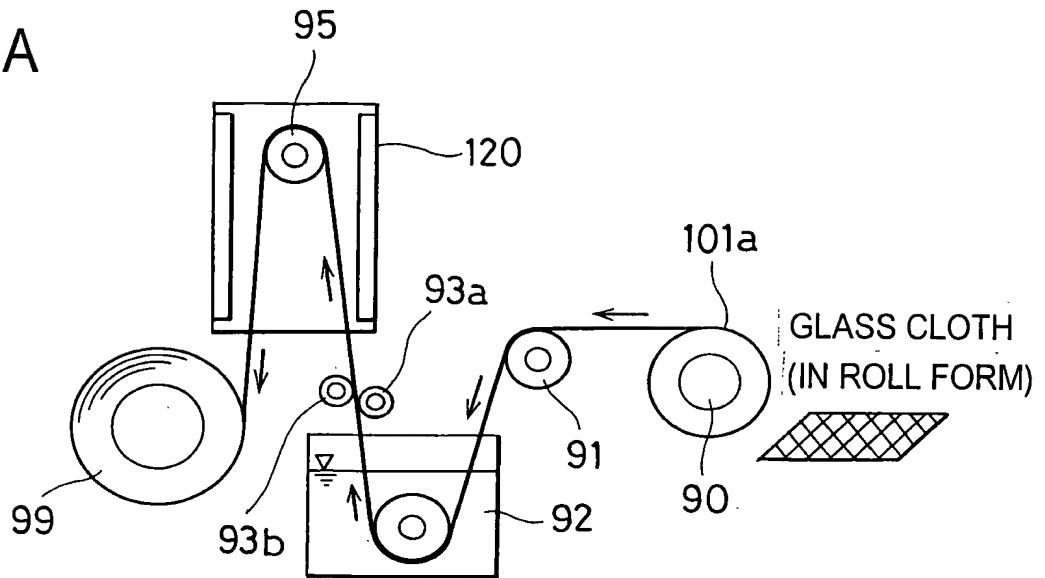


FIG. 81B

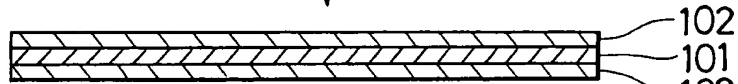


FIG. 81C

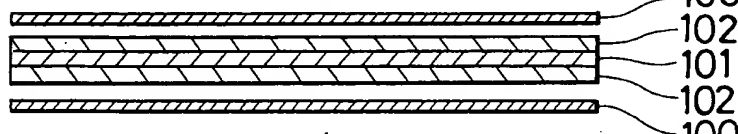
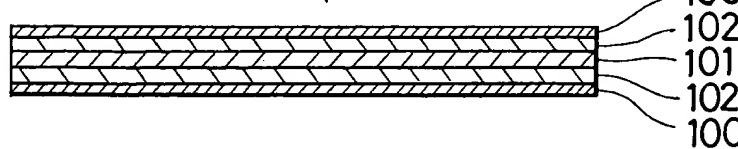


FIG. 81D



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FIG. 82A

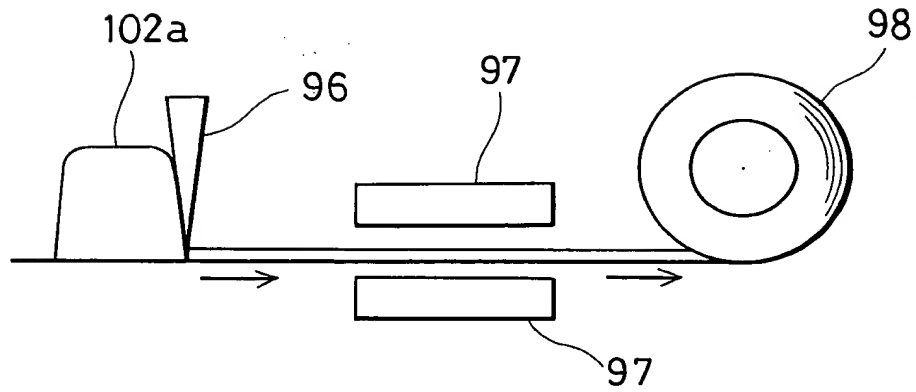


FIG. 82B

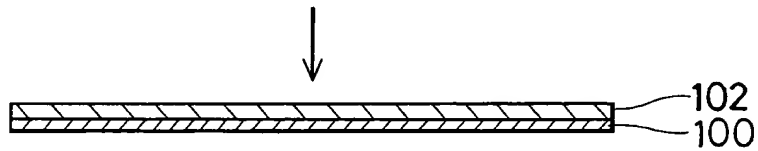


FIG. 82C

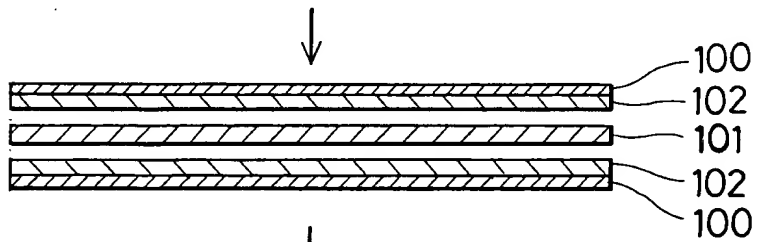
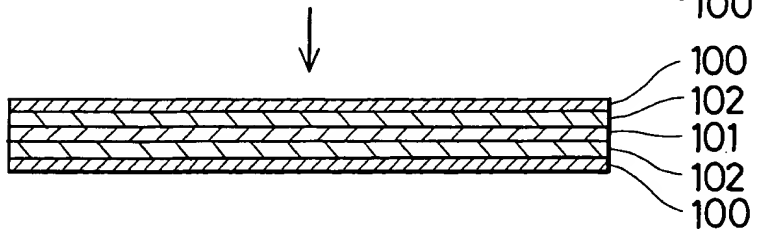
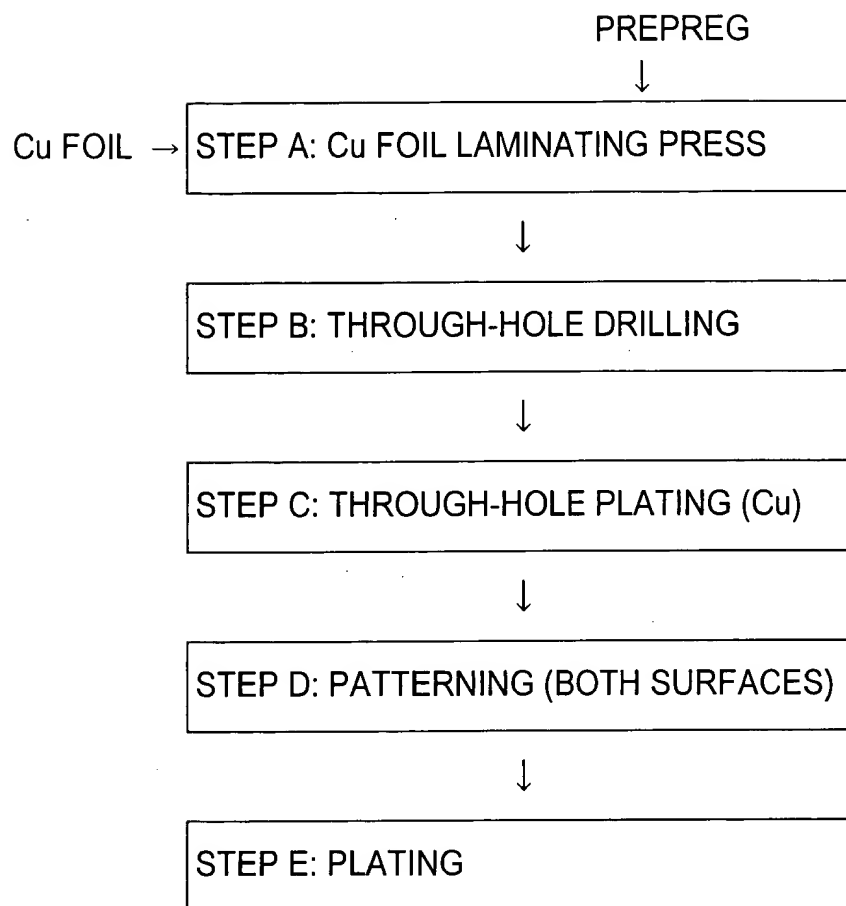


FIG. 82D



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FIG. 83

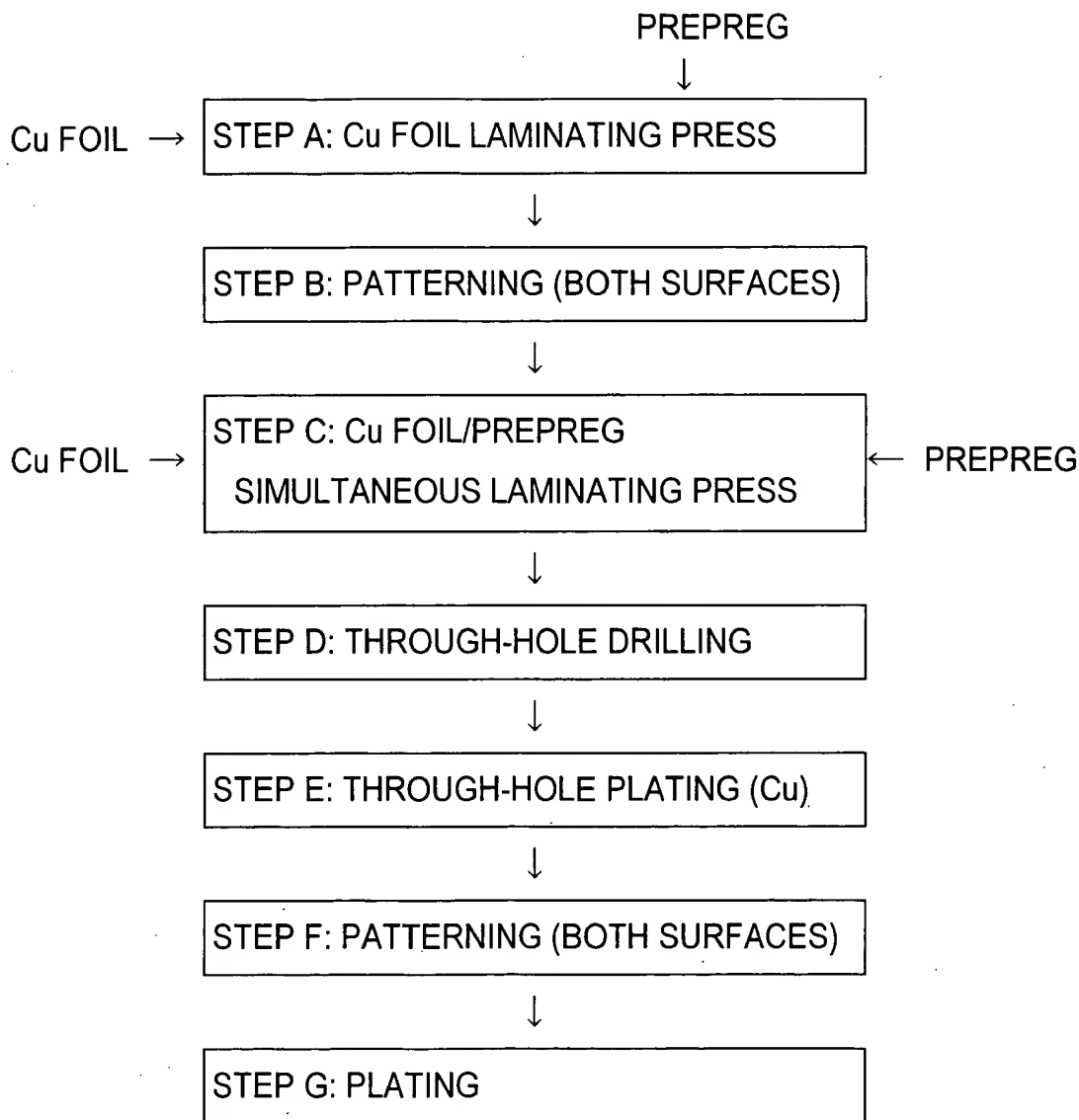


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Figure 1 illustrates a sequence of four cross-sectional diagrams (STEP A, STEP B, STEP C, STEP D) showing the manufacturing process of a semiconductor device.

- STEP A:** A substrate 216 is shown. A layer 217 is being deposited on the top surface of the substrate 216.
- STEP B:** The layer 217 is patterned into a central region 218, with side regions 217 remaining.
- STEP C:** The side regions 217 are further processed, possibly etched or planarized, leaving a central region 218 and side regions 217.
- STEP D:** The final structure is shown, featuring a central region 218 and side regions 217. Additional layers 225 and 226 are added to the top surface.

FIG. 85



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Figure 1 illustrates a sequence of steps (STEP A to STEP F) in the manufacturing of a semiconductor device, showing cross-sectional views of the structure at each stage.

- STEP A:** A substrate 217 is shown. A layer 216 is being deposited onto the substrate.
- STEP B:** The layer 216 is shown with openings 224.
- STEP C:** The layer 216 is shown with openings 224. A new layer 216 is being deposited.
- STEP D:** The layer 216 is shown with openings 224. A new layer 216 is being deposited.
- STEP E:** The layer 216 is shown with openings 224. A new layer 216 is being deposited.
- STEP F:** The final structure is shown, featuring a central gap 219 and openings 224.

FIG. 87A

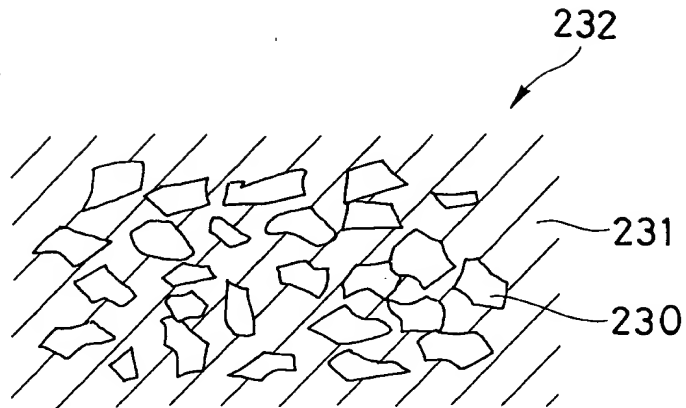


FIG. 87B

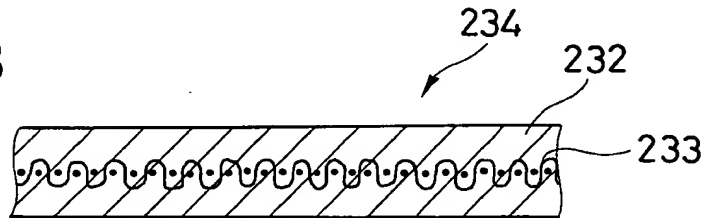
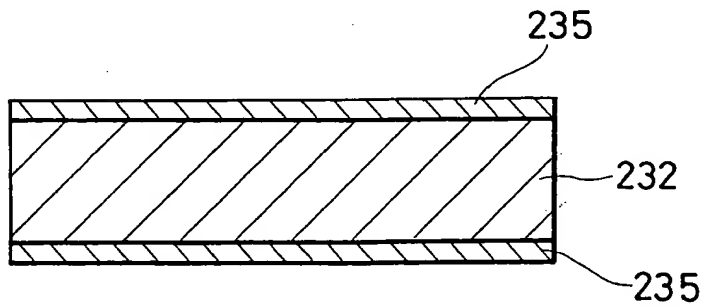


FIG. 87C



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FIG. 88A

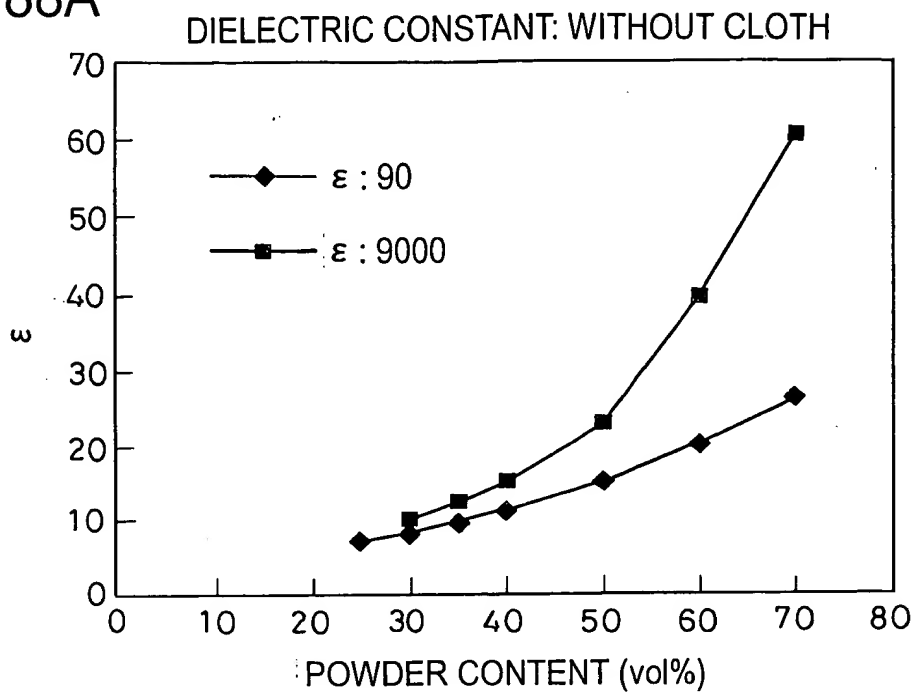


FIG. 88B

